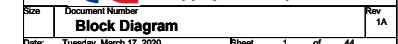


01

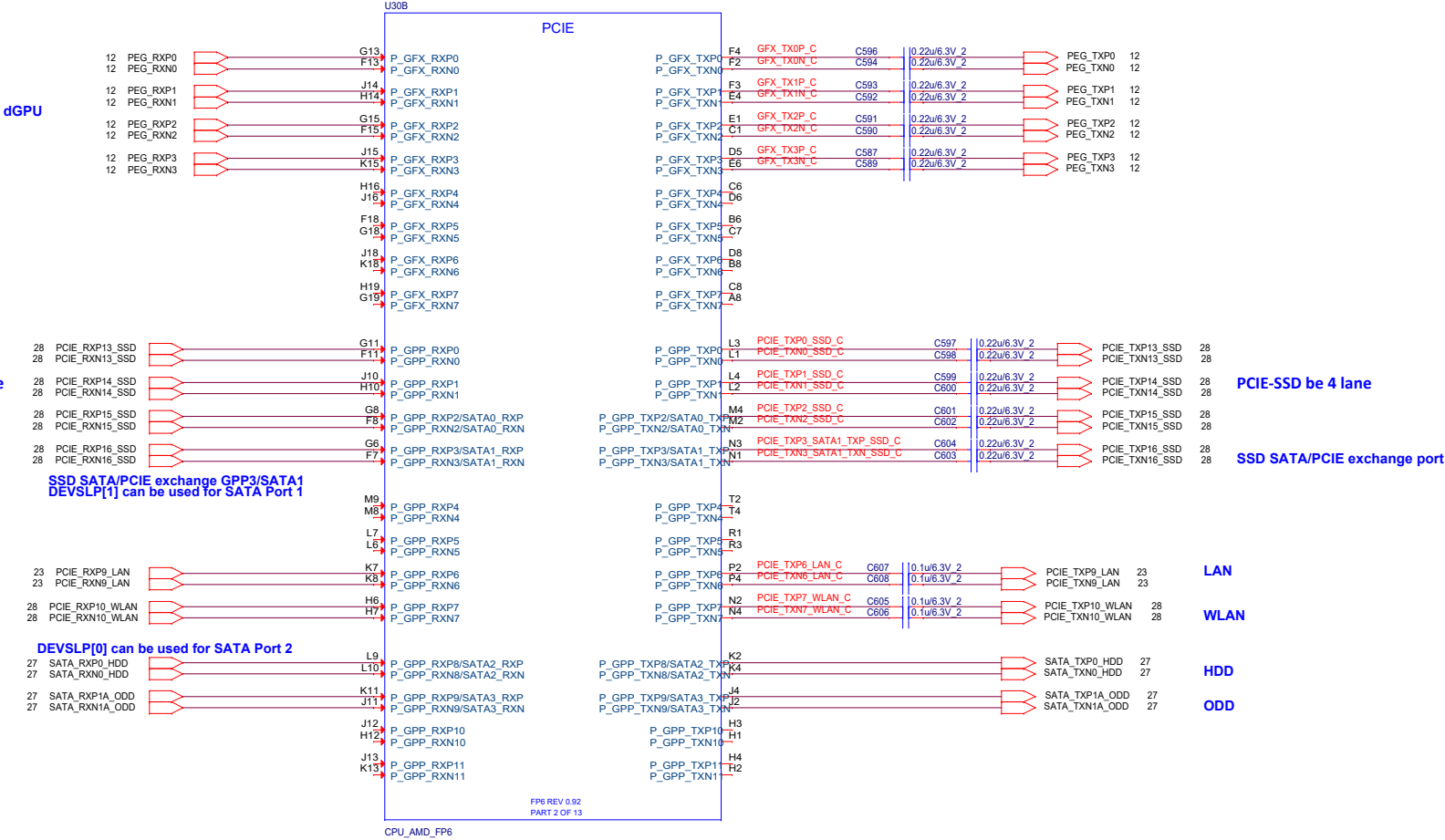


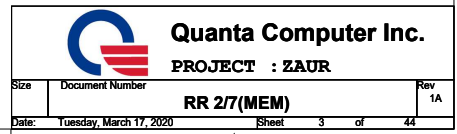
APU PCIE

AMD APU	TOP BSQ	QBCON

PCIE Port	Function
PCIE_0	SSD_PCIE
PCIE_1	SSD_PCIE
PCIE_2	SSD_PCIE
PCIE_3	SSD_PCIE
PCIE_4	NA
PCIE_5	NA
PCIE_6	LAN
PCIE_7	WLAN

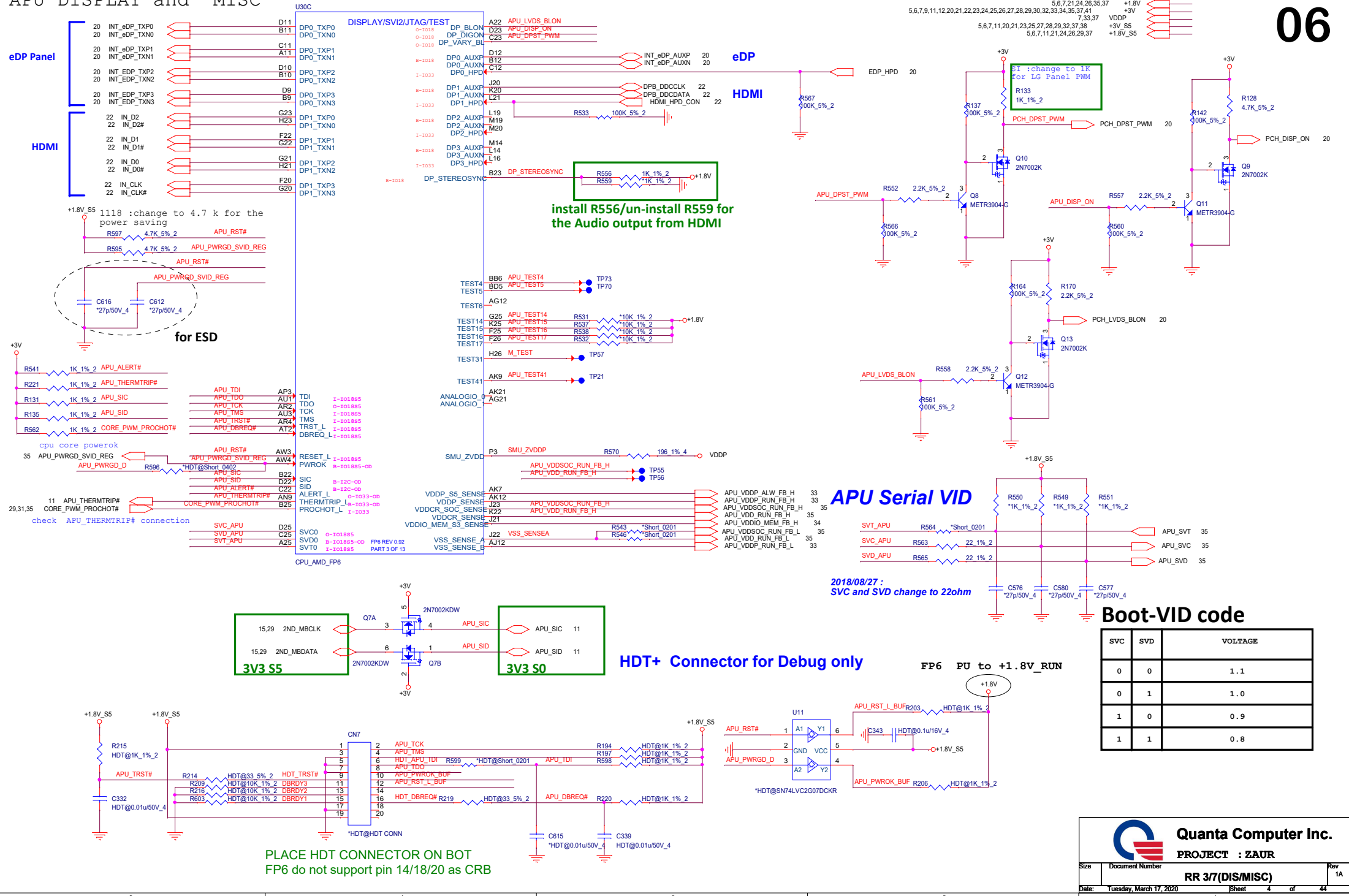
SATA Port	Function
SATA_1	M.2_SSD
SATA_2	HDD
SATA_3	ODD





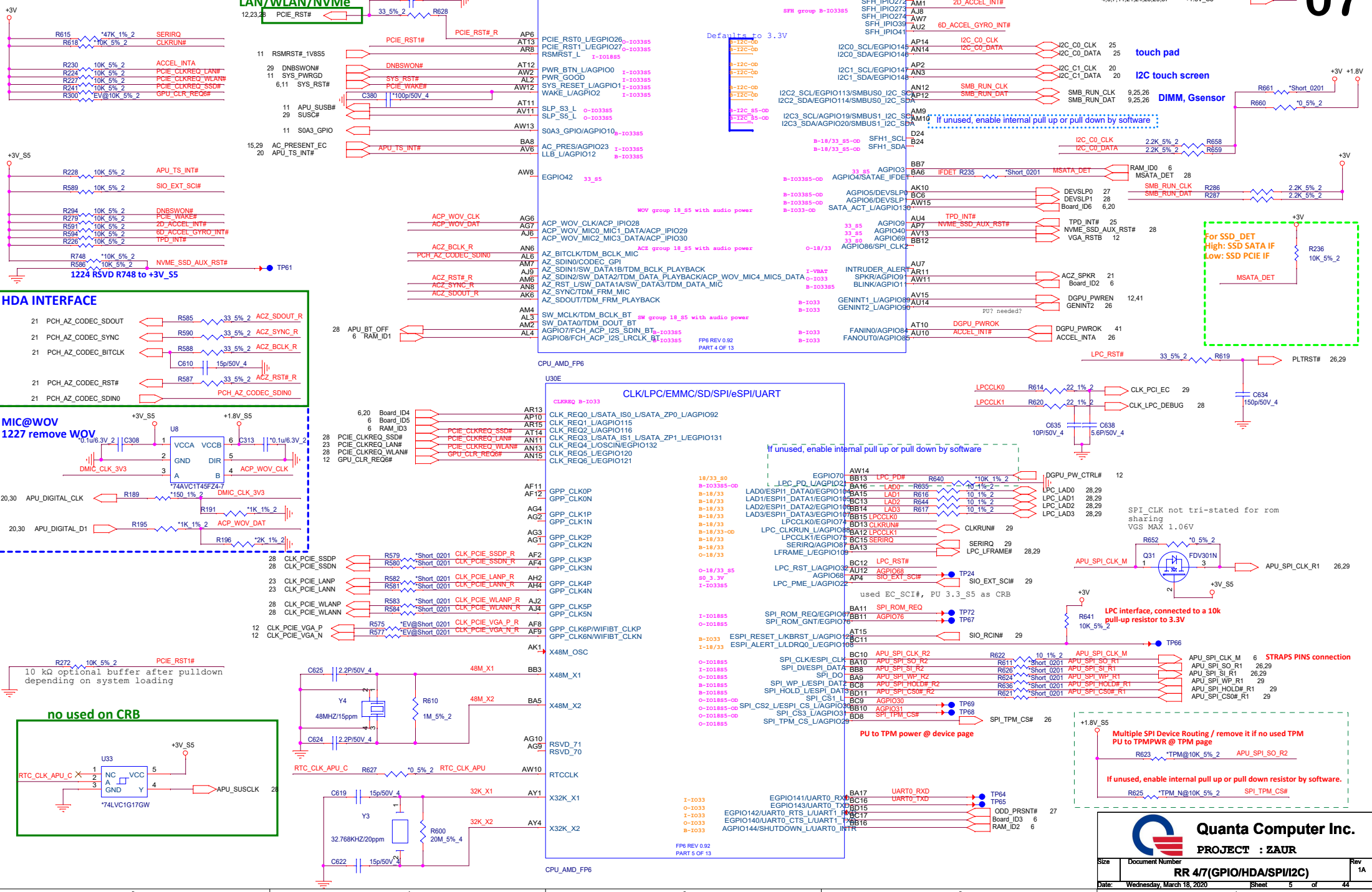
APU DISPLAY and MISC

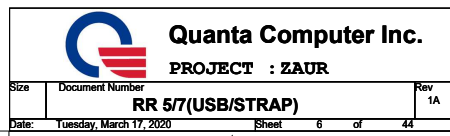
06



APU GPIO/AZ/UART

07

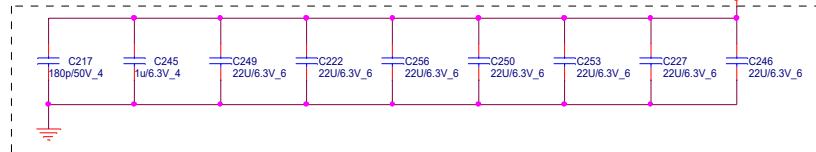




APU POWER

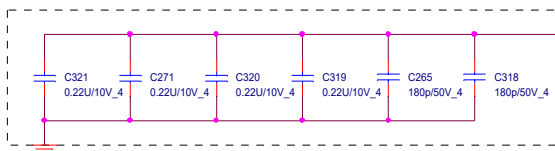
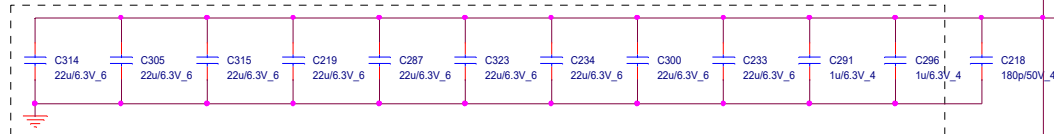
09

BOTTOM SIDE DECOUPLING UNDER APU



RR DG: 9*22UF+2*1UF+4*0.22uf+3*180PF

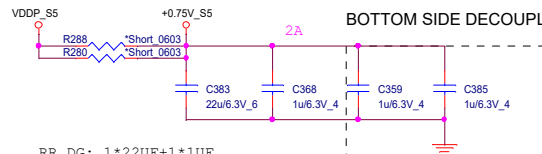
BOTTOM SIDE DECOUPLING UNDER APU



If the VSS plane is cut to create a VDDIO_MEM_S3 plane, ceramic capacitors with NP0 or COG dielectric are connected across the VDDIO_MEM_S3 and VSS plane split.

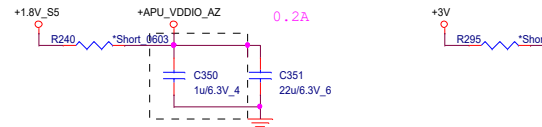
RR DG: 1*22UF+3*1UF

BOTTOM SIDE DECOUPLING UNDER APU



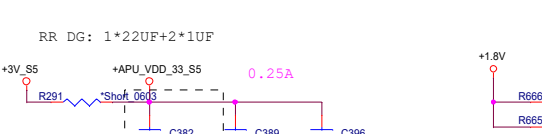
RR DG: 1*22UF+1*1UF

BOTTOM SIDE DECOUPLING UNDER APU



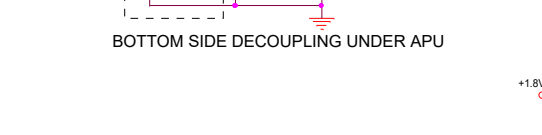
RR DG: 1*22UF+2*1UF

BOTTOM SIDE DECOUPLING UNDER APU



RR DG: 1*22UF+2*1UF

BOTTOM SIDE DECOUPLING UNDER APU



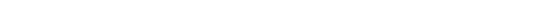
RR DG: 1*22UF+2*1UF

BOTTOM SIDE DECOUPLING UNDER APU



RR DG: 1*22UF+2*1UF

BOTTOM SIDE DECOUPLING UNDER APU



RR DG: 1*22UF+2*1UF

BOTTOM SIDE DECOUPLING UNDER APU

RR DG: 1*22UF+2*1UF

BOTTOM SIDE DECOUPLING UNDER APU

RR DG: 1*22UF+2*1UF

BOTTOM SIDE DECOUPLING UNDER APU

RR DG: 1*22UF+2*1UF

BOTTOM SIDE DECOUPLING UNDER APU

RR DG: 1*22UF+2*1UF

BOTTOM SIDE DECOUPLING UNDER APU

RR DG: 1*22UF+2*1UF

BOTTOM SIDE DECOUPLING UNDER APU

RR DG: 1*22UF+2*1UF

BOTTOM SIDE DECOUPLING UNDER APU

RR DG: 1*22UF+2*1UF

BOTTOM SIDE DECOUPLING UNDER APU

RR DG: 1*22UF+2*1UF

BOTTOM SIDE DECOUPLING UNDER APU

RR DG: 1*22UF+2*1UF

BOTTOM SIDE DECOUPLING UNDER APU

RR DG: 1*22UF+2*1UF

BOTTOM SIDE DECOUPLING UNDER APU

RR DG: 1*22UF+2*1UF

BOTTOM SIDE DECOUPLING UNDER APU

RR DG: 1*22UF+2*1UF

BOTTOM SIDE DECOUPLING UNDER APU

RR DG: 1*22UF+2*1UF

BOTTOM SIDE DECOUPLING UNDER APU

RR DG: 1*22UF+2*1UF

BOTTOM SIDE DECOUPLING UNDER APU

RR DG: 1*22UF+2*1UF

BOTTOM SIDE DECOUPLING UNDER APU

RR DG: 1*22UF+2*1UF

BOTTOM SIDE DECOUPLING UNDER APU

RR DG: 1*22UF+2*1UF

BOTTOM SIDE DECOUPLING UNDER APU

RR DG: 1*22UF+2*1UF

BOTTOM SIDE DECOUPLING UNDER APU

RR DG: 1*22UF+2*1UF

BOTTOM SIDE DECOUPLING UNDER APU

RR DG: 1*22UF+2*1UF

BOTTOM SIDE DECOUPLING UNDER APU

RR DG: 1*22UF+2*1UF

BOTTOM SIDE DECOUPLING UNDER APU

RR DG: 1*22UF+2*1UF

BOTTOM SIDE DECOUPLING UNDER APU

RR DG: 1*22UF+2*1UF

BOTTOM SIDE DECOUPLING UNDER APU

RR DG: 1*22UF+2*1UF

BOTTOM SIDE DECOUPLING UNDER APU

RR DG: 1*22UF+2*1UF

BOTTOM SIDE DECOUPLING UNDER APU

RR DG: 1*22UF+2*1UF

BOTTOM SIDE DECOUPLING UNDER APU

RR DG: 1*22UF+2*1UF

BOTTOM SIDE DECOUPLING UNDER APU

RR DG: 1*22UF+2*1UF

BOTTOM SIDE DECOUPLING UNDER APU

RR DG: 1*22UF+2*1UF

BOTTOM SIDE DECOUPLING UNDER APU

RR DG: 1*22UF+2*1UF

BOTTOM SIDE DECOUPLING UNDER APU

RR DG: 1*22UF+2*1UF

BOTTOM SIDE DECOUPLING UNDER APU

RR DG: 1*22UF+2*1UF

BOTTOM SIDE DECOUPLING UNDER APU

RR DG: 1*22UF+2*1UF

BOTTOM SIDE DECOUPLING UNDER APU

RR DG: 1*22UF+2*1UF

BOTTOM SIDE DECOUPLING UNDER APU

RR DG: 1*22UF+2*1UF

BOTTOM SIDE DECOUPLING UNDER APU

RR DG: 1*22UF+2*1UF

BOTTOM SIDE DECOUPLING UNDER APU

RR DG: 1*22UF+2*1UF

BOTTOM SIDE DECOUPLING UNDER APU

RR DG: 1*22UF+2*1UF

BOTTOM SIDE DECOUPLING UNDER APU

RR DG: 1*22UF+2*1UF

BOTTOM SIDE DECOUPLING UNDER APU

RR DG: 1*22UF+2*1UF

BOTTOM SIDE DECOUPLING UNDER APU

RR DG: 1*22UF+2*1UF

BOTTOM SIDE DECOUPLING UNDER APU

RR DG: 1*22UF+2*1UF

BOTTOM SIDE DECOUPLING UNDER APU

RR DG: 1*22UF+2*1UF

BOTTOM SIDE DECOUPLING UNDER APU

RR DG: 1*22UF+2*1UF

BOTTOM SIDE DECOUPLING UNDER APU

RR DG: 1*22UF+2*1UF

BOTTOM SIDE DECOUPLING UNDER APU

RR DG: 1*22UF+2*1UF

BOTTOM SIDE DECOUPLING UNDER APU

RR DG: 1*22UF+2*1UF

BOTTOM SIDE DECOUPLING UNDER APU

RR DG: 1*22UF+2*1UF

BOTTOM SIDE DECOUPLING UNDER APU

RR DG: 1*22UF+2*1UF

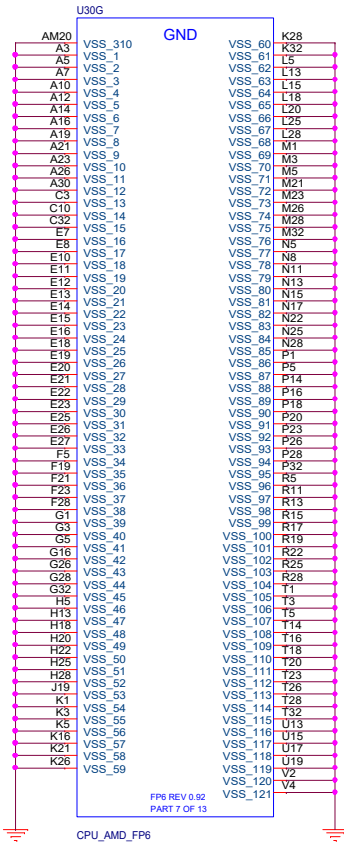
BOTTOM SIDE DECOUPLING UNDER APU

RR DG: 1*22UF+2*1UF

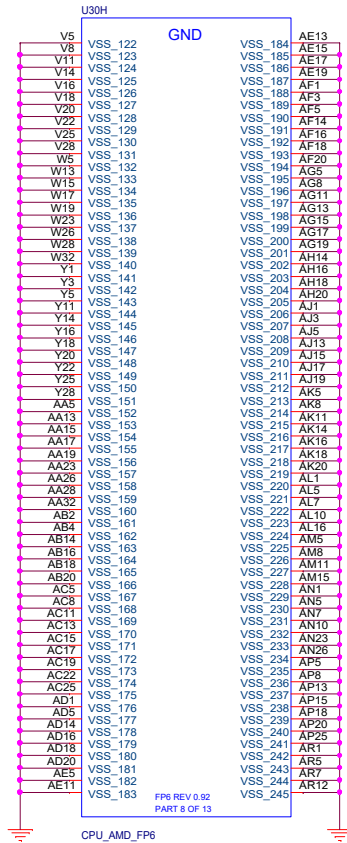
BOTTOM SIDE DECOUPLING UNDER APU

RR DG: 1*22UF+2*1UF

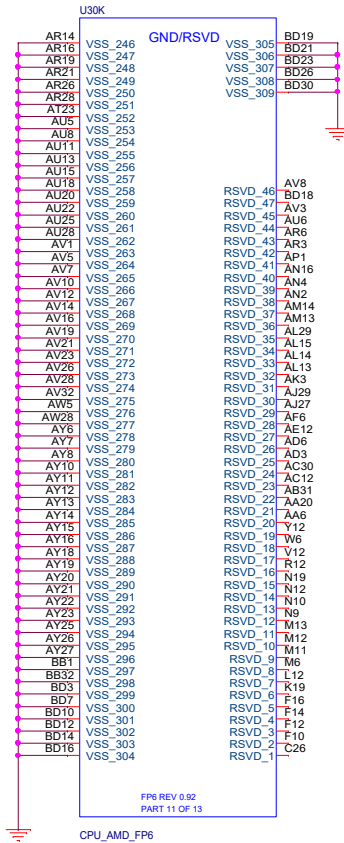
BOTTOM SIDE DECOUPLING UNDER APU

FP6 REV 0.92
PART 7 OF 13

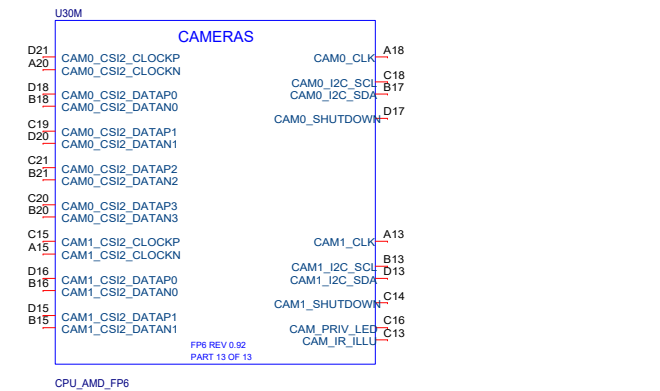
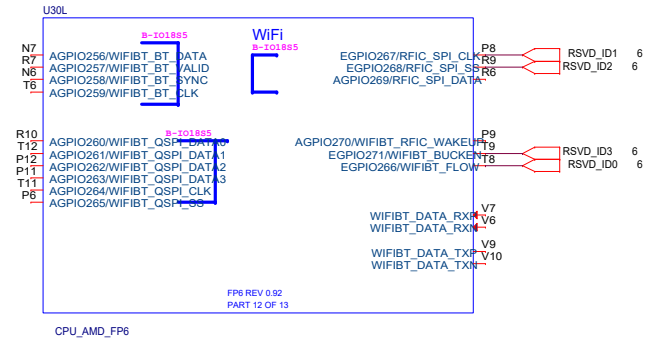
CPU_AMD_FP6

FP6 REV 0.92
PART 8 OF 13

CPU_AMD_FP6

FP6 REV 0.92
PART 11 OF 13

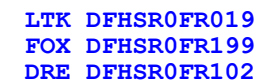
CPU_AMD_FP6

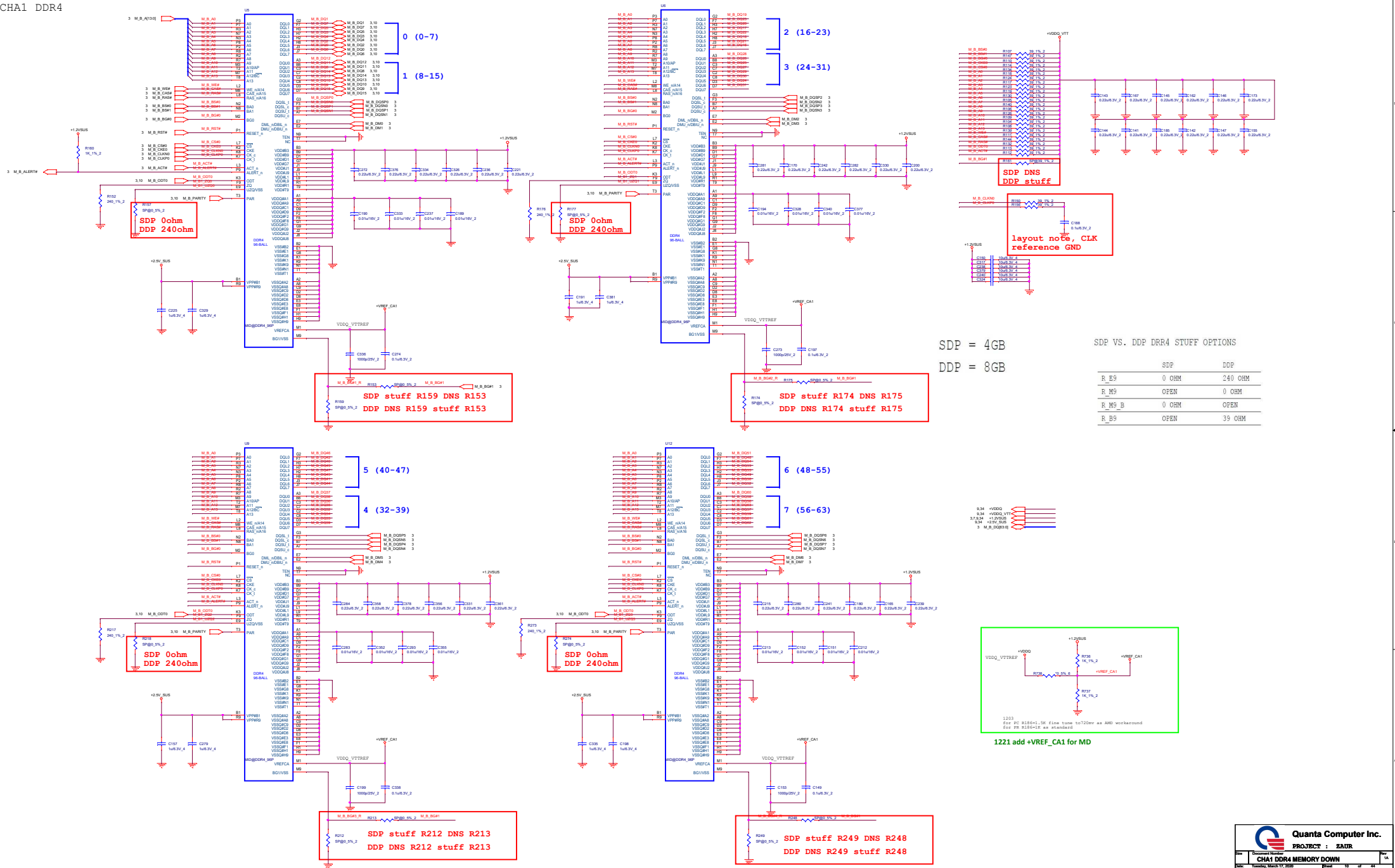


Quanta Computer Inc.

PROJECT : ZAUR

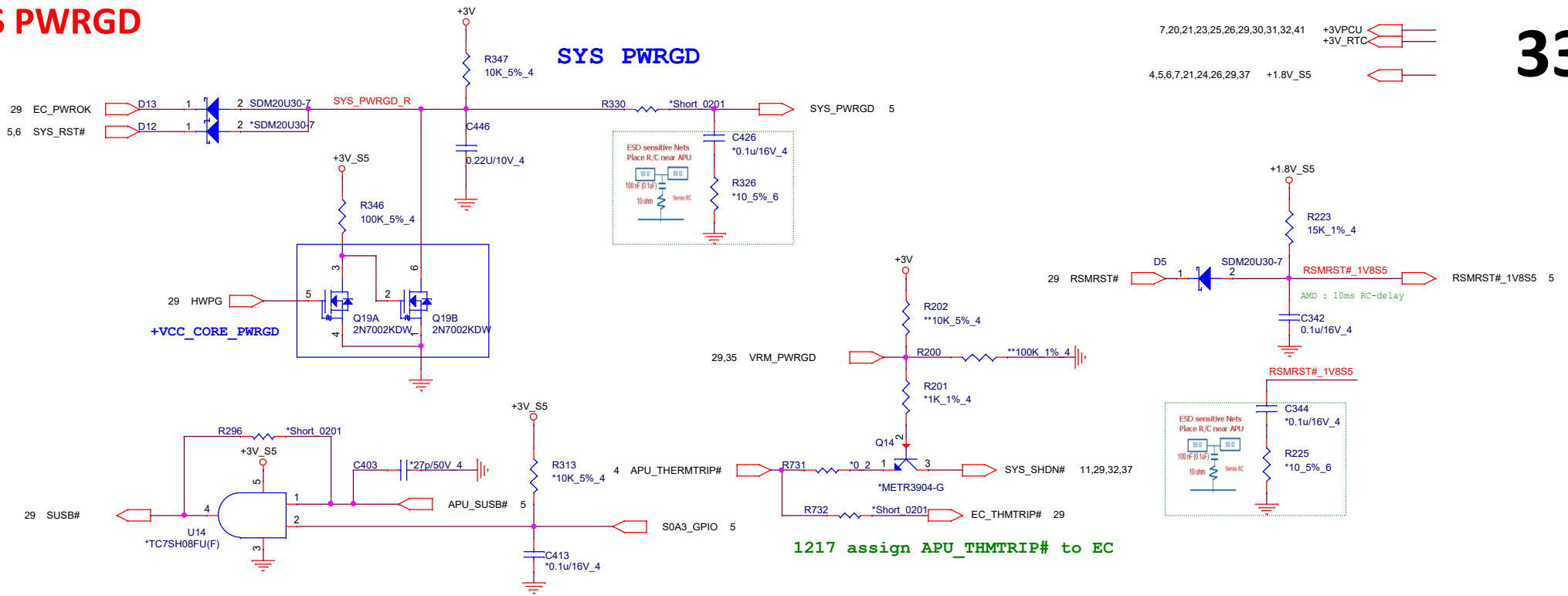
Size	Document Number	Rev
	RR 77(GND/RSVD)	1A
Date:	Tuesday, March 17, 2020	Sheet 8 of 44



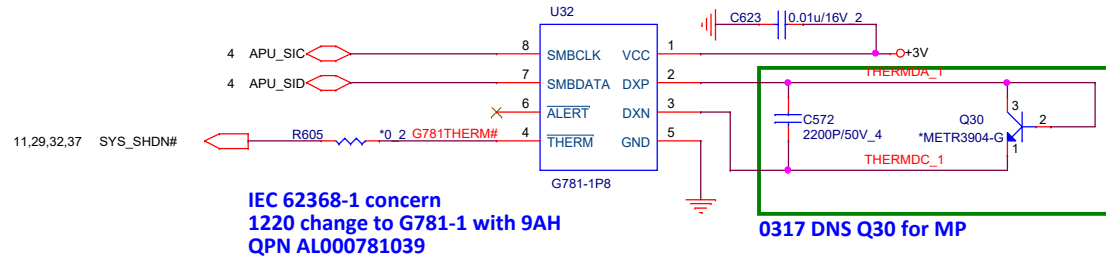


SYS_PWRGD

SYS_PWRGD

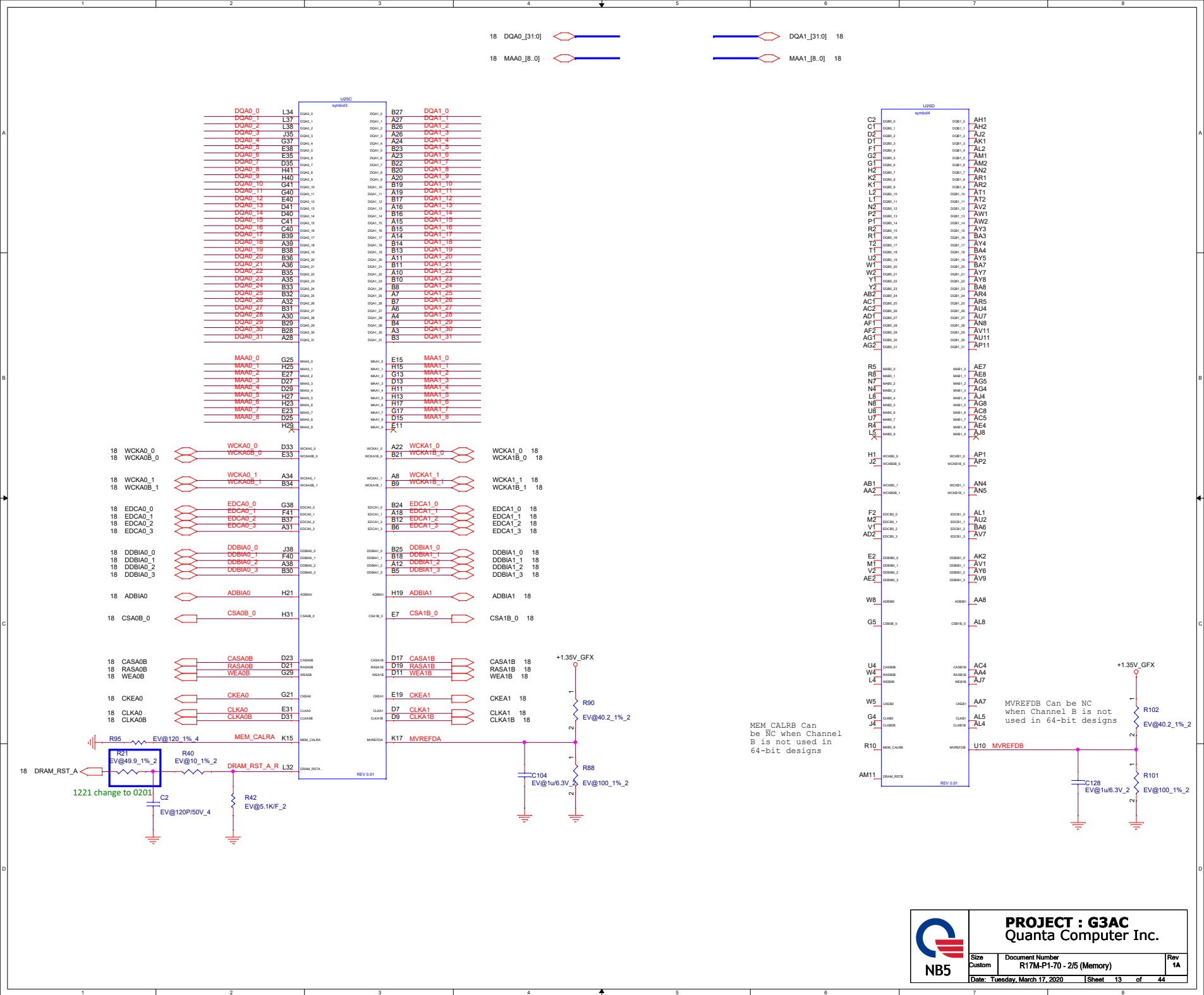


Address 9AH

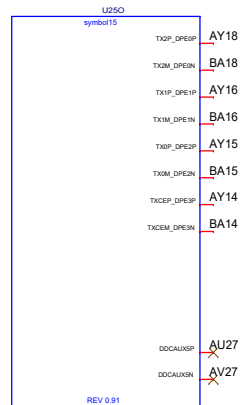


Quanta Computer Inc.
PROJECT : ZAUR

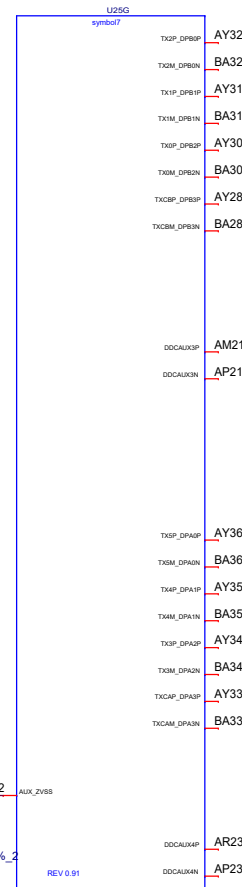
Size	Document Number	Rev
	RR SYSPWRGD/ThermalSensor	1A
Date:	Tuesday, March 17, 2020	Sheet 11 of 44



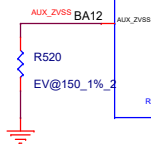
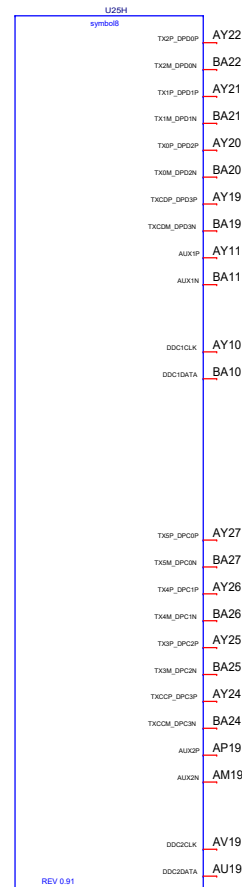
ASIC - TMDP (E)




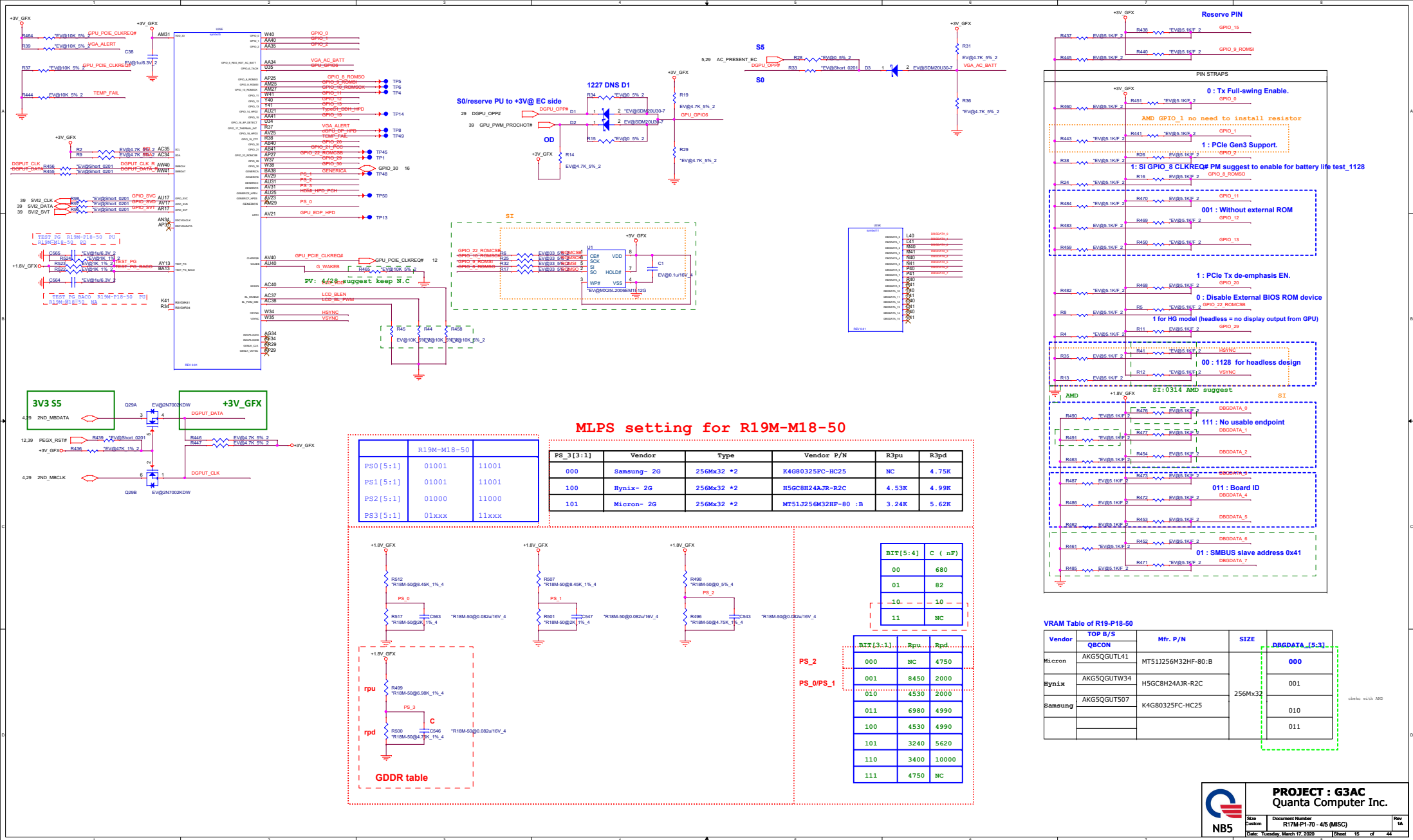
ASIC - TMDP (A/B)

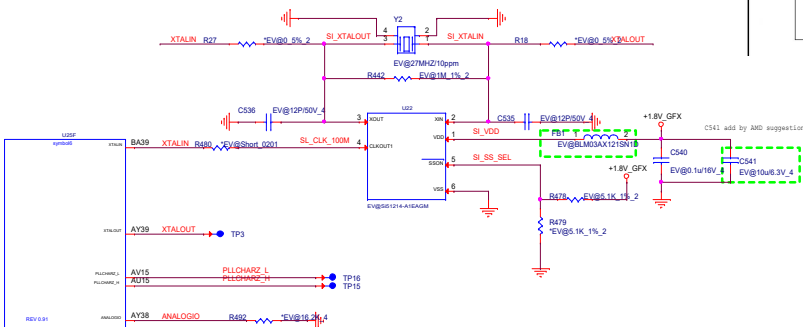
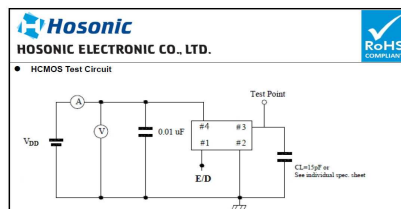
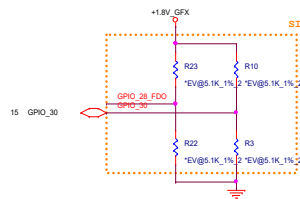
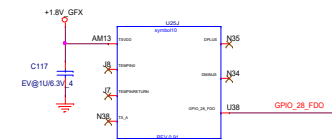


ASIC - TMDP (C/D)



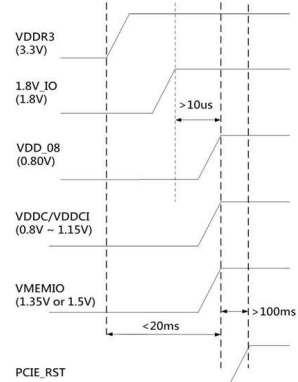
	PROJECT : G3AC Quanta Computer Inc.	
	Size A3	Document Number R17M-P1-70- 3/5 (Display)
	Date: Tuesday, March 17, 2020	Sheet 14 of 44



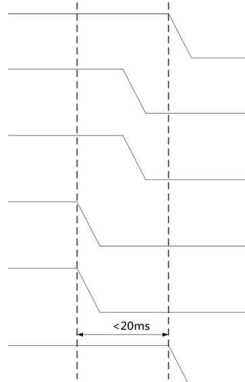


R10M-G1-10 Power up sequence for you refer:

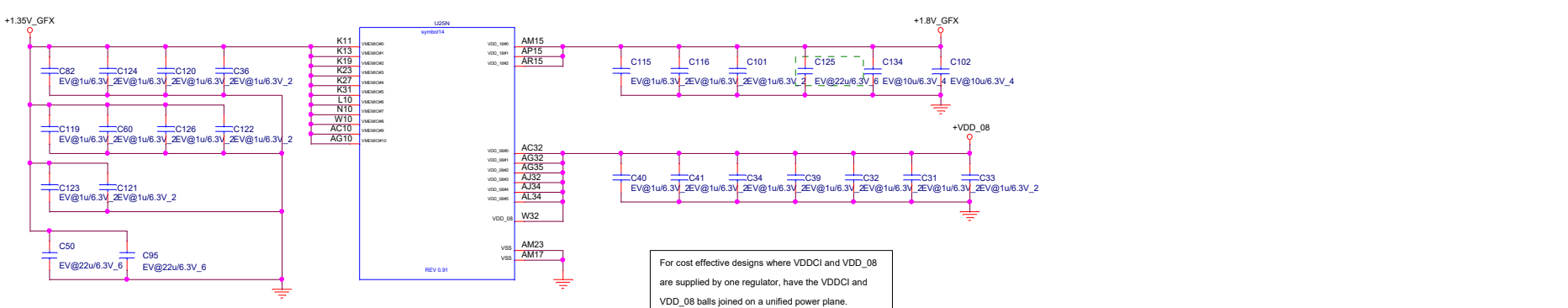
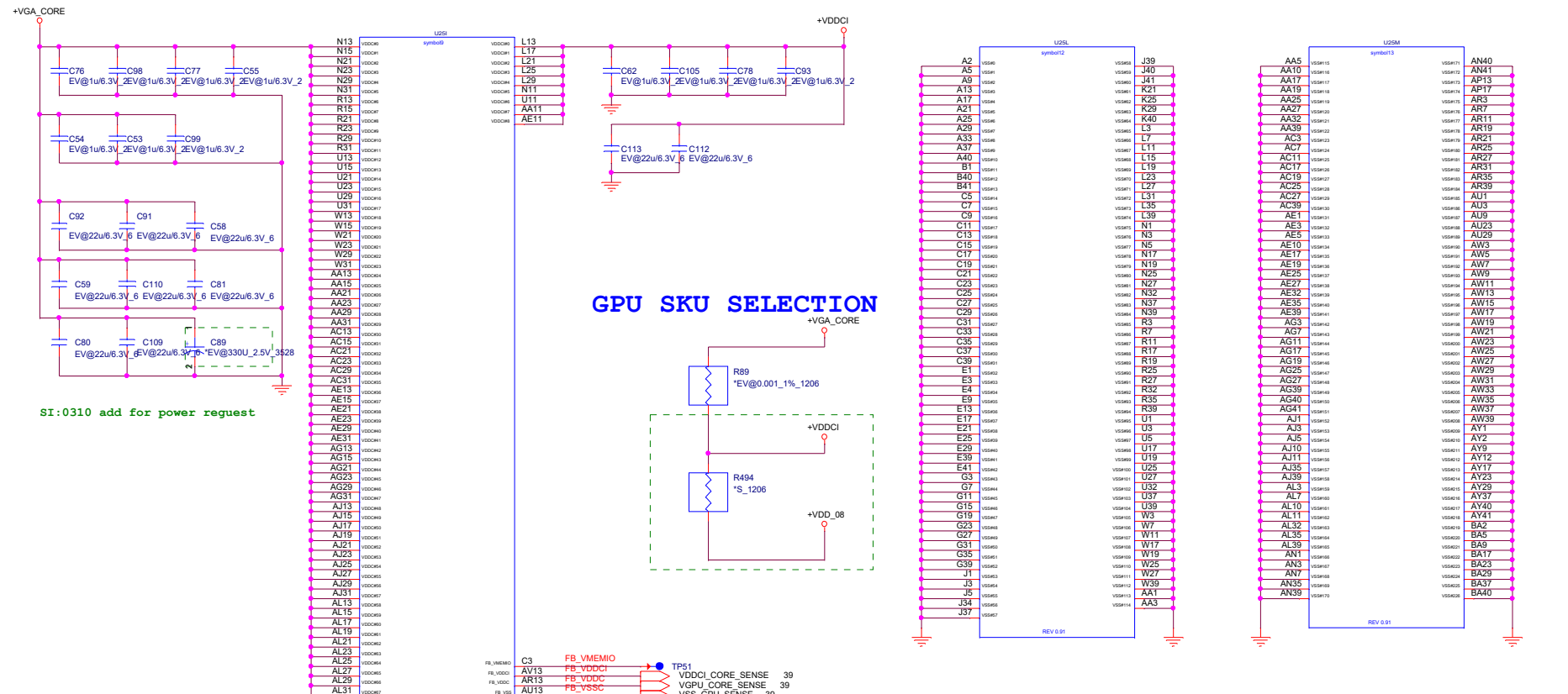
POWER UP

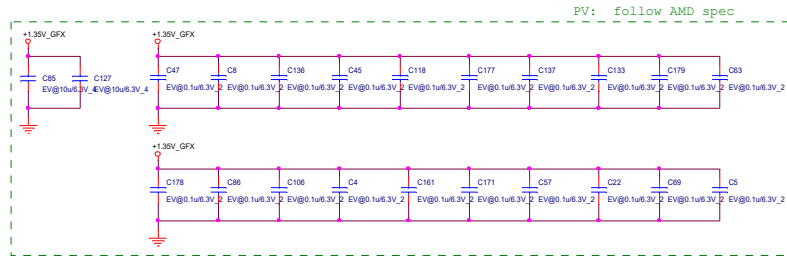
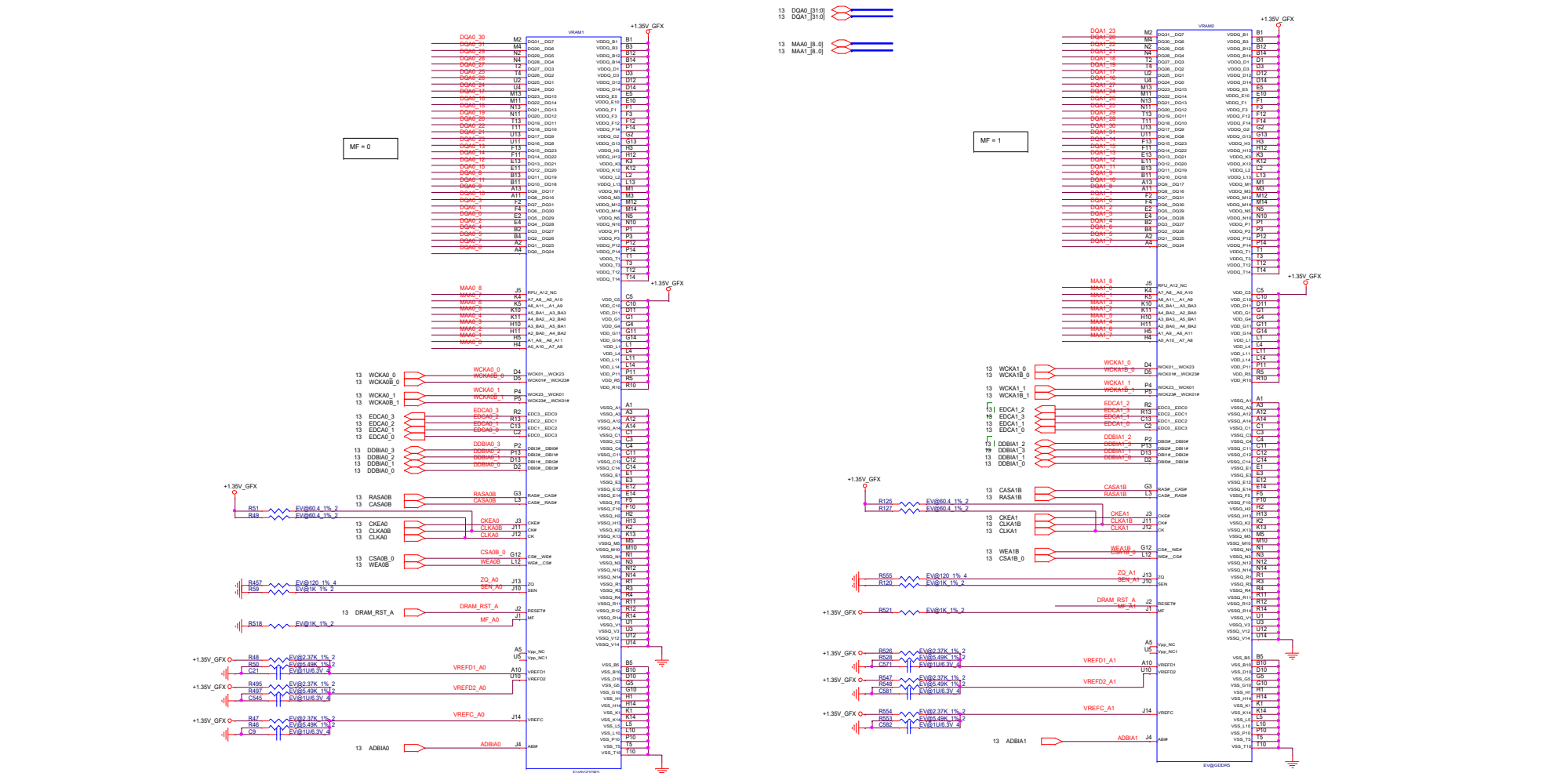


POWER DOWN

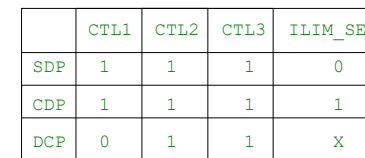


AMD GPIO Strapping	Setting	Name	Description
GPIO 29	Pull low 10K ohm	BIF_VGA_DIS	0: VGA Controller capacity enabled. 1: The device will not be recognized as the system's VGA controller (for headless designs).
GPIO 20	Pull up 10K ohm	TX_DEEMPH_EN	PCI Express transmitter deemphasis enable 0: Tx de-emphasis disabled. 1: Tx de-emphasis enabled.
GPIO 0	Pull up 10K ohm	TX_HALF_SWING	Controls the transmitter full/half swing mode. 0: The transmitter full swing is enabled. 1: The transmitter half swing is enabled.
GPIO 22	Pull low 10K ohm	BIOS_ROM_EN	Enable external BIOS ROM device. 0: Disable external BIOS ROM device. 1: Enable external BIOS ROM device.
GPIO 11	Pull up 10K ohm	ROM_CONFIG[2:0]	b) If BIOS_ROM_EN = 0, then ROM_CONFIG[2:0] defines the primary memory aperture size. GPIO_1[3:2:1]=001=256MB
GPIO 12	Pull low 10K ohm		
GPIO 13	Pull low 10K ohm		
Hsync	NC	Reserve	Reserve
Vsync	NC	Reserve	Reserve
DBGDATA2	Pull up 10K ohm	AUD_PORT_CONN [2:0]	Determine the maximum number of digital display audio endpoints 101: Two usable endpoints
DBGDATA1	Pull low 10K ohm		
DBGDATA0	Pull up 10K ohm		
GPIO 1	Pull up 10K ohm	SMBUS_ADDR	Provide a strap option to change the SMBUS slave address of the GPU. 0: 0x40 1: 0x41
GPIO 2	Pull up 10K ohm	BIF_GEN3_EN_A	PCIe Gen3 capability. 1: PCIe Gen3 is supported. 0: PCIe Gen3 is not supported.
GPIO 8	connect CLKREQ#_GPU and add pull up / down resistor	BIF_CLK_PM_EN (Reserve)	Determines whether or not the PCIe reference clock power management capability is reported in the PCI configuration space (otherwise known as CLKREQB). 0: The CLKREQB power management capability is disabled. 1: The CLKREQB power management capability is enabled.
WAKEB	Pull low 10K ohm	OBFF	0: Disable
SVI2_SVC	Pull up 1Kohm	Boot up voltage	SVC:SVI2=[1:0]=0.90V
SVI2_SVD	Pull low 1K ohm		





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RILIM_LO is optional and the ILM_LO pin may be left unconnected if the following conditions are met:

1. ILM_SEL is always set high
2. Load Detection - Port Power Management is not used
3. Mouse / Keyboard wake function is not used

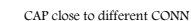
If conditions 1 and 2 are met but the mouse / keyboard wake function is also desired, it is recommended to use RILIM_LO < 80.6 kΩ.

The following equation programs the typical current limit:

$$I_{OS_typ}(mA) = 50,250 / \{RILIM_XX(k\Omega) + 0.1\}$$

(1)
 RILIM_XX corresponds to either RILIM_HI or RILIM_LO as appropriate.

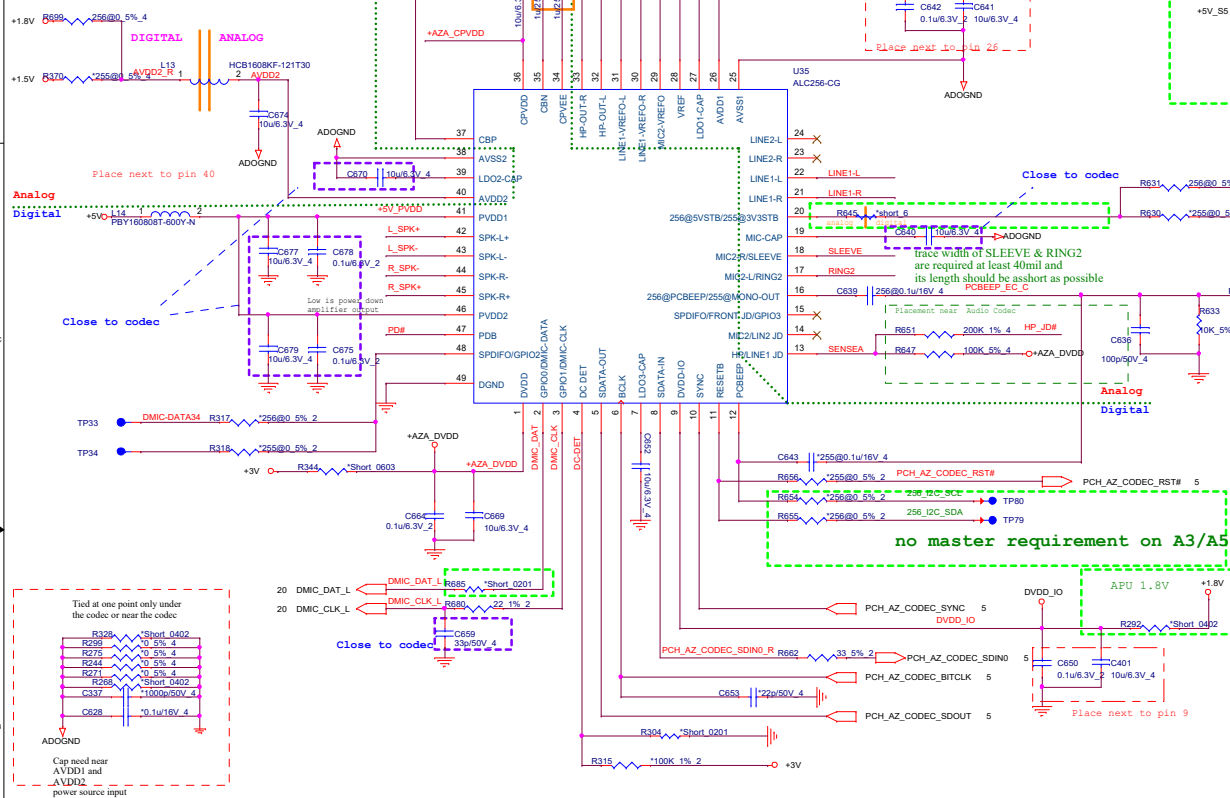
USB protection diodes for ESD,
as close as possible to USB connector pins.



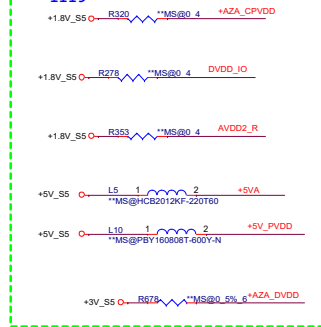
Codec(ADO)

CPVDD PWR

Codec PWR 1.8V(ADO)



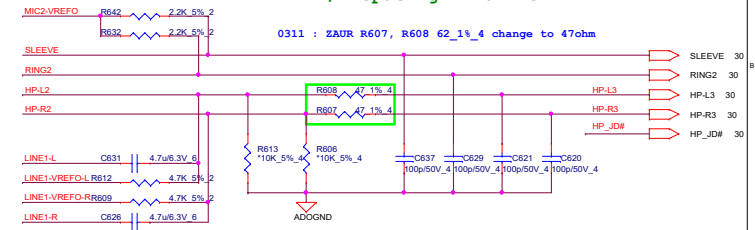
1119



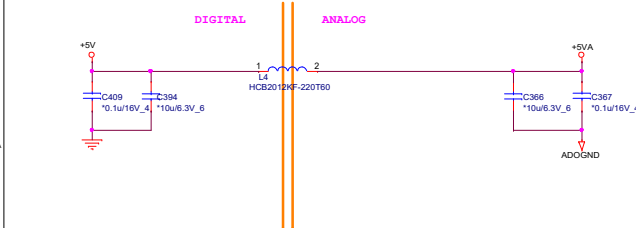
WW G2 @ ALC256 : AL000256009
 MGF G3 @ ALC3256M:
 ALC255 : AL000255000- Design reserved

Universal Audio Jack HEADPHONE/MIC/LINE combo (ADO)

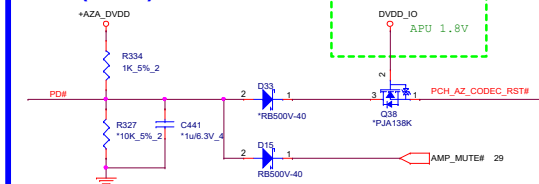
SLEEVE/RING2 trace > 40mils
 HP/LINE trace > 10mils
 L/R spacing > 10mils



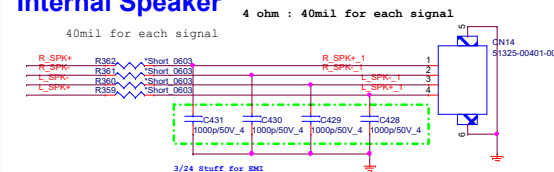
Codec PWR 5V(ADO)



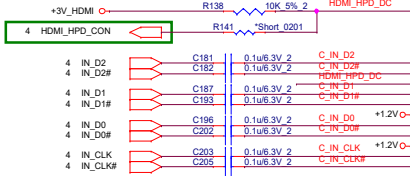
Mute(ADO)



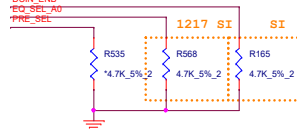
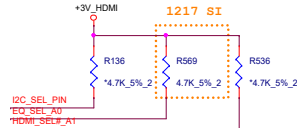
Internal Speaker



HDMI_HPD PD100K @ APU side



PS8409 strap pin



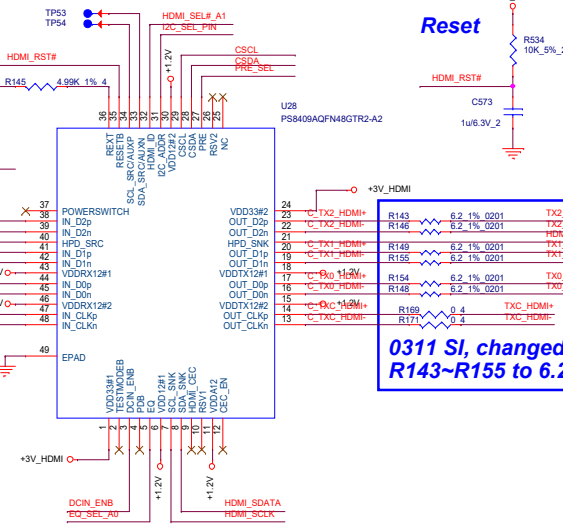
DCIN_ENB
DC coupling enable; Internal pull up, 3.3V I/O.
L: DC coupling input
H: Default, AC coupling input

EQ_SEL_A0
Receiver equalization setting; Internal pull up, 3.3V I/O.
L: Compensation for channel loss up to 13dB
H: Default, Compensation for channel loss up to 17dB
M: Compensation for channel loss up to 11dB

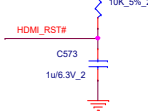
PRE_SEL
Output pre-emphasis setting; Internal pull up, 3.3V I/O.
L: Pre-emphasis =2.5dB
H: Default, No Pre-emphasis

HDMI_SEL# A1
HDMI ID enable; Internal pull down, 3.3V I/O.
L: Default, HDMI ID enable
H: HDMI ID disable

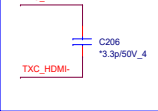
I2C_SEL_PIN
I2C Slave Address selection; Internal pull down, 3.3V I/O.
L: Default, Slave address 0x10-0x2F.
H: Alternative slave address 0x90-0x9F, 0xD0-0xDF.



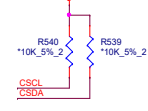
Reset



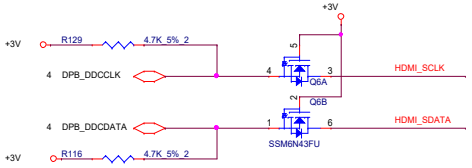
Reserve



Optional



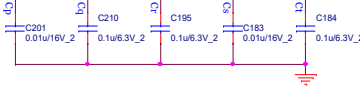
0311 SI, changed R129, R116 to 4.7K



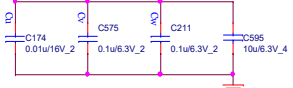
Place Ci,Cj,Ck close to U12 pin7,11
Place Ci,Cm,Cn,Co close to U12 pin46



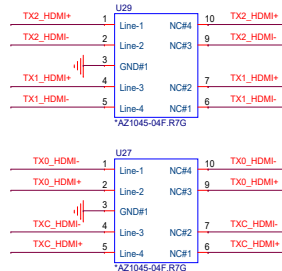
Place Cp,Cq,Cr close to U12 pin15,18
Place Cs,Ct close to U12 pin30



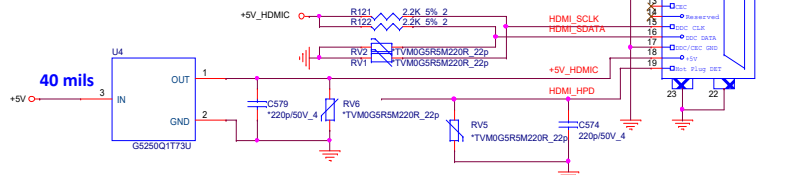
Place Cu,Cv close to U12 pin24
Place Cw close to U12 pin1



For ESD
Layout note: Place close to HDMI Conn

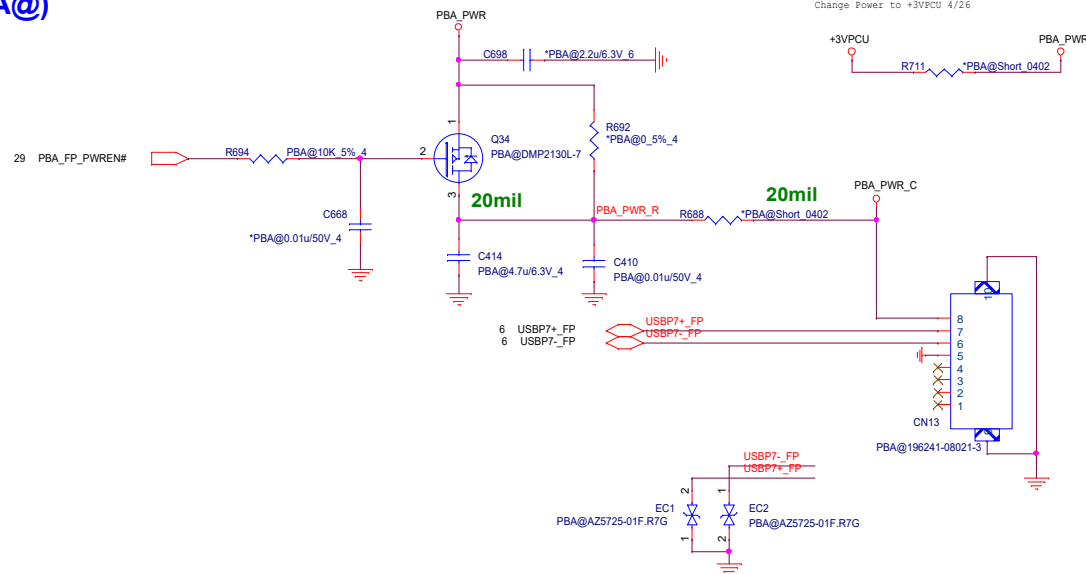


Layout note: Place close to HDMI Conn



23

[illegible]

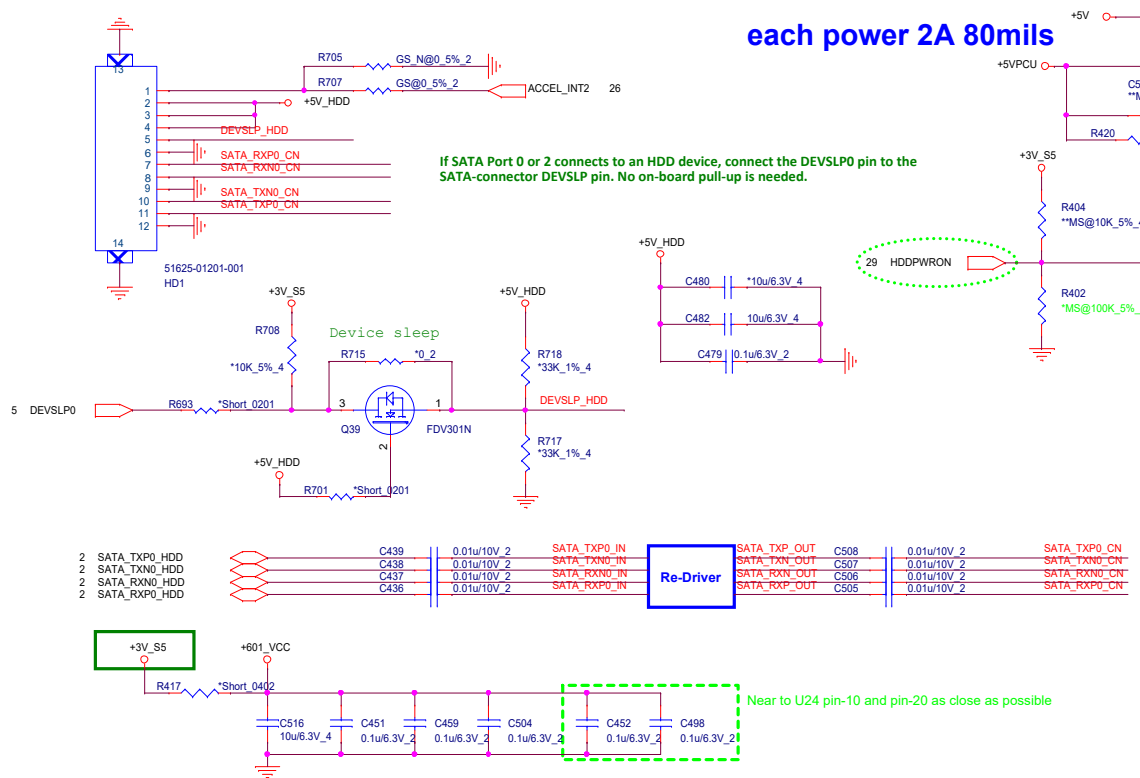


M.S SATA SSD devices should be powered from S5 rail during S0i3, and should support DEVSLP as well as HIPM functionality. The SATA SSD power should be gated by EC GPIO during S3, S4, and S5.

	19,21,24,30,32,34,35,39	+5V_ S5
	20,21,22,25,32,37	+5V
4,5,6,7,9,11,12,20,21,22,23,24,25,26,28,29,30,32,33,34,35,37,41		+3V
	5,6,7,11,20,21,23,25,28,29,32,37,38	+3V S5



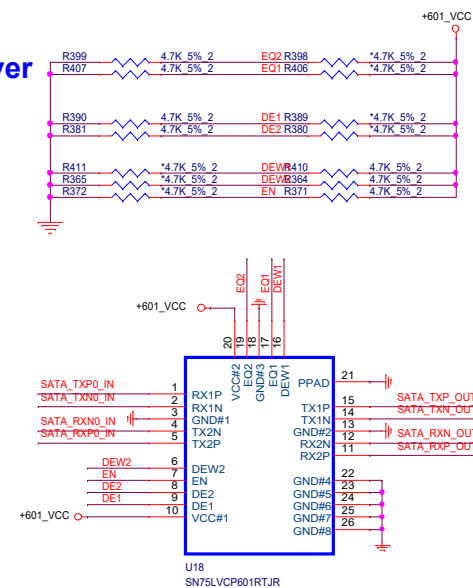
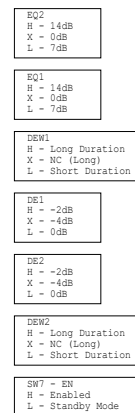
27



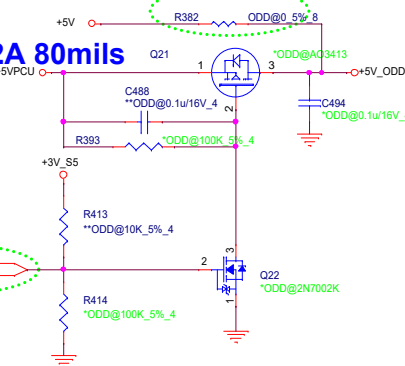
each power 2A 80mils

1227 remove MS, short R400, DNS Q23

SATA HDD Re-driver



each power 2A 80mils

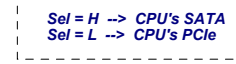


M.S EC assignment reserved
A3/A5 do not support ODD



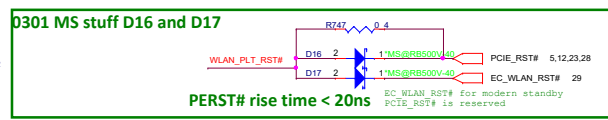
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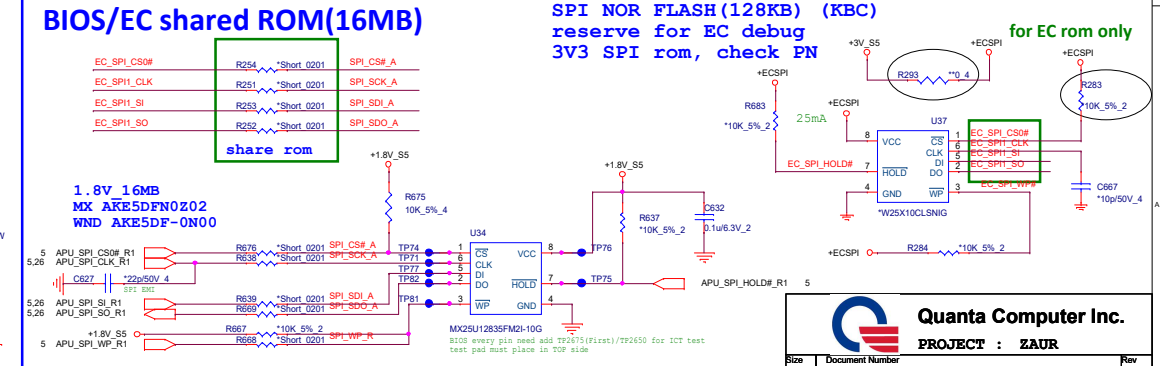
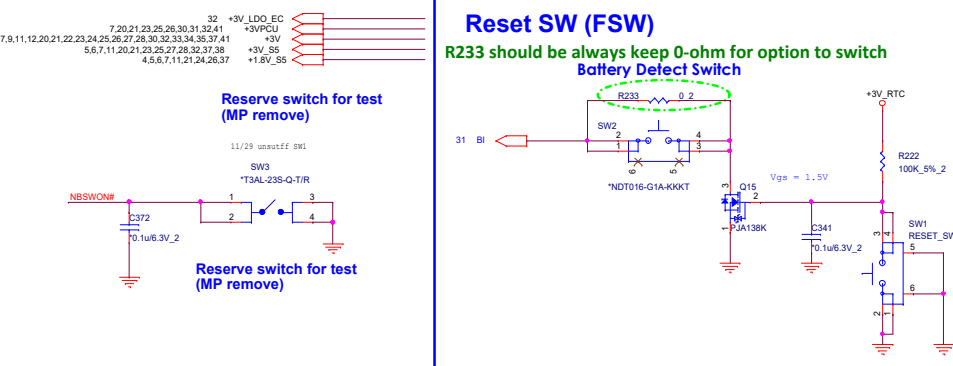
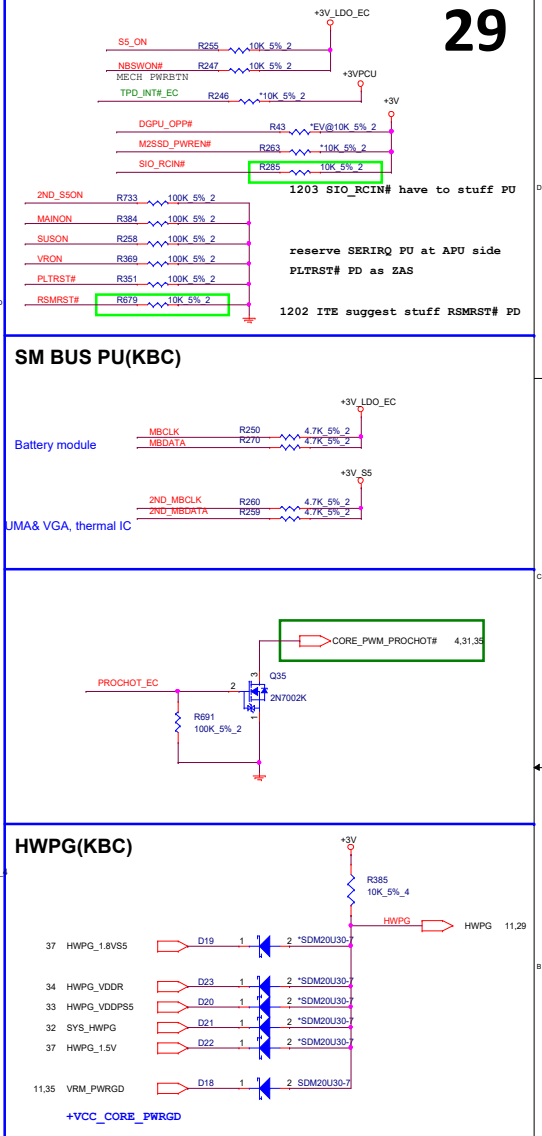
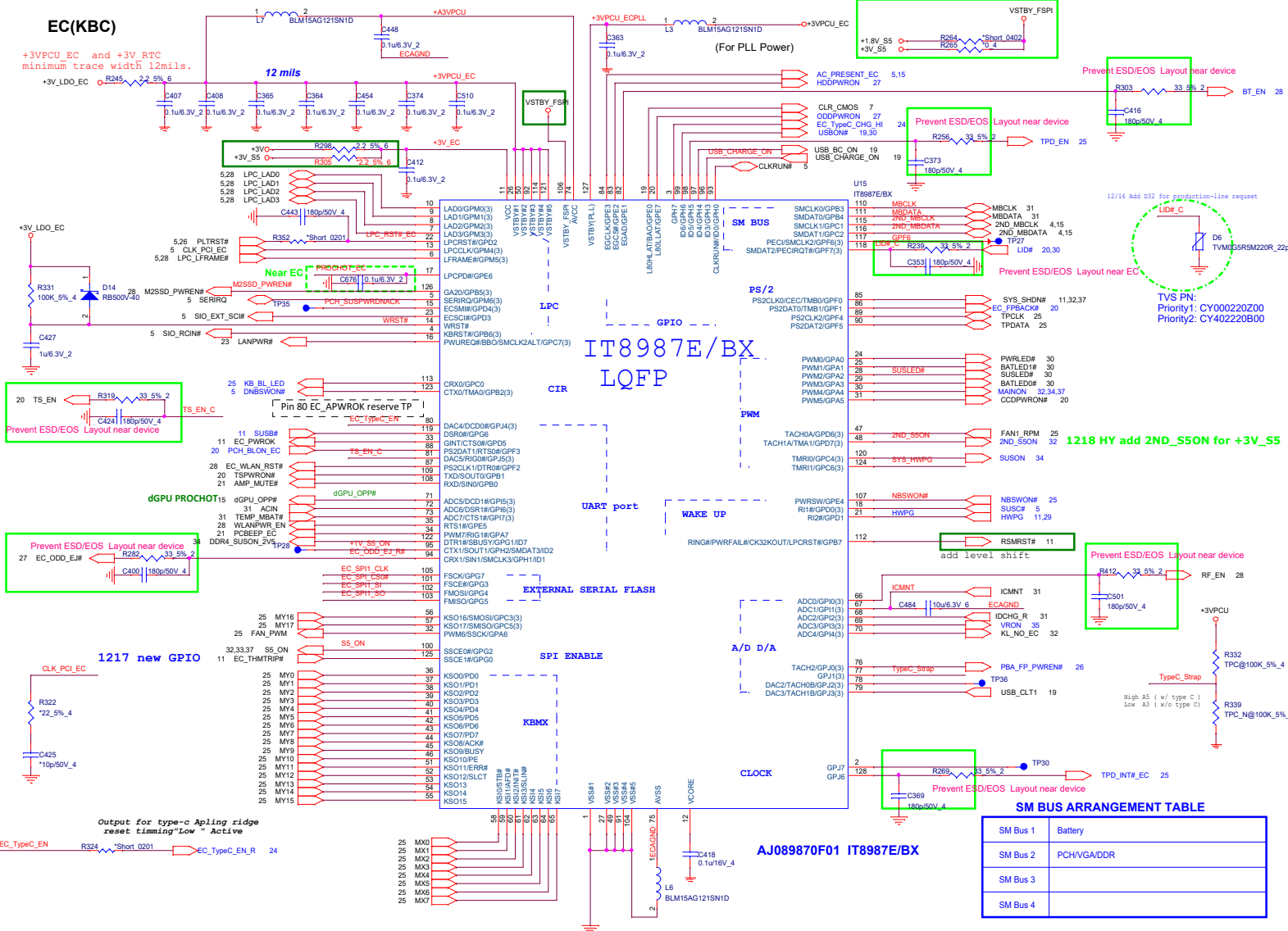
M2SSD_PWREN SHOULD COME FROM EC
M.S NVMe (PCIe or M.2) devices should be powered by S0 rail to reduce power consumption in MS.
SATA SSD should be powered by S5 rail as SATA SSD has DEVSPLP feature to reduce power consumption.

M.S Design in S5 power domain .
M.S Add Wake/INT GPIO pin.
M.S Add Aux Reset GPIO pin AND-gate with PCI_RST0_L

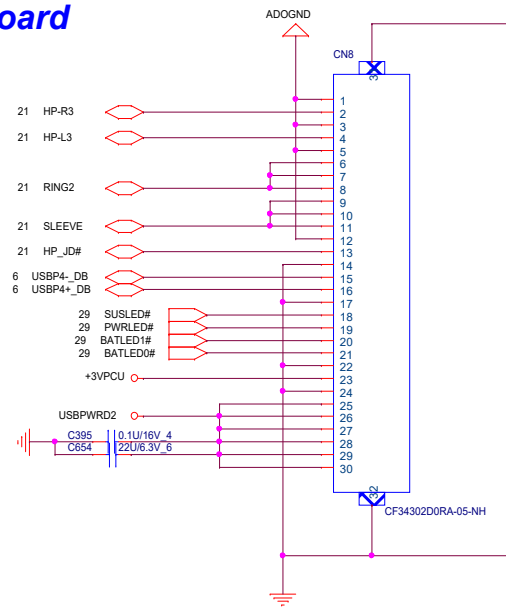


10K_5%_2 1227 BT_EN changed to APU

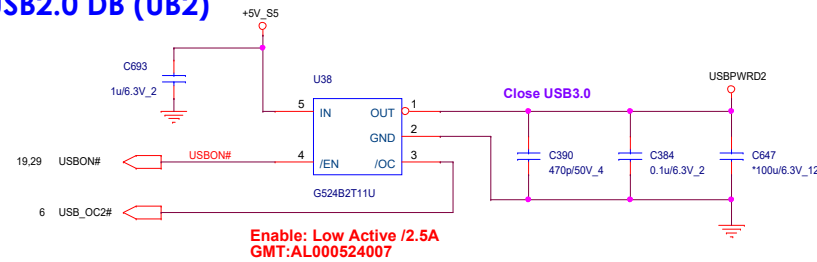
EC(KBC)



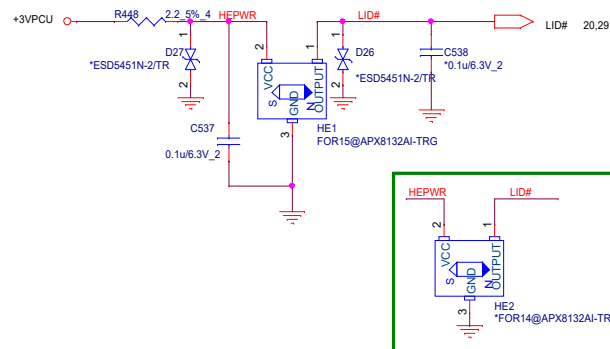
USB Board



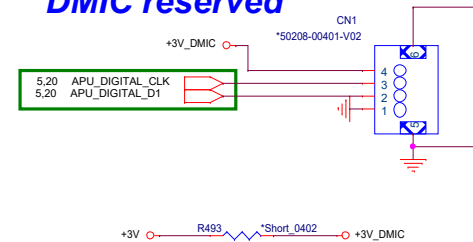
USB2.0 DB (UB2)



Hall Sensor



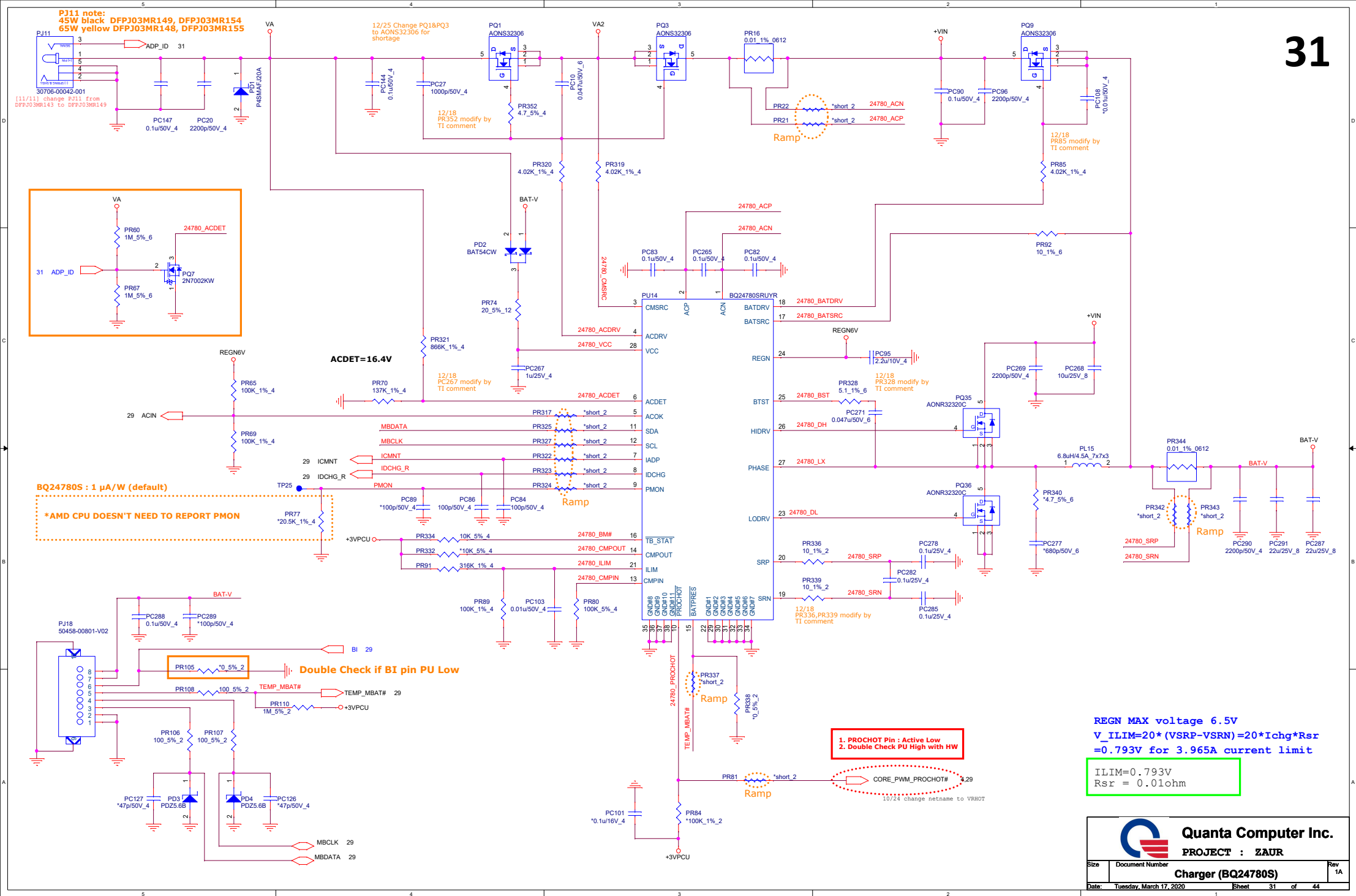
DMIC reserved

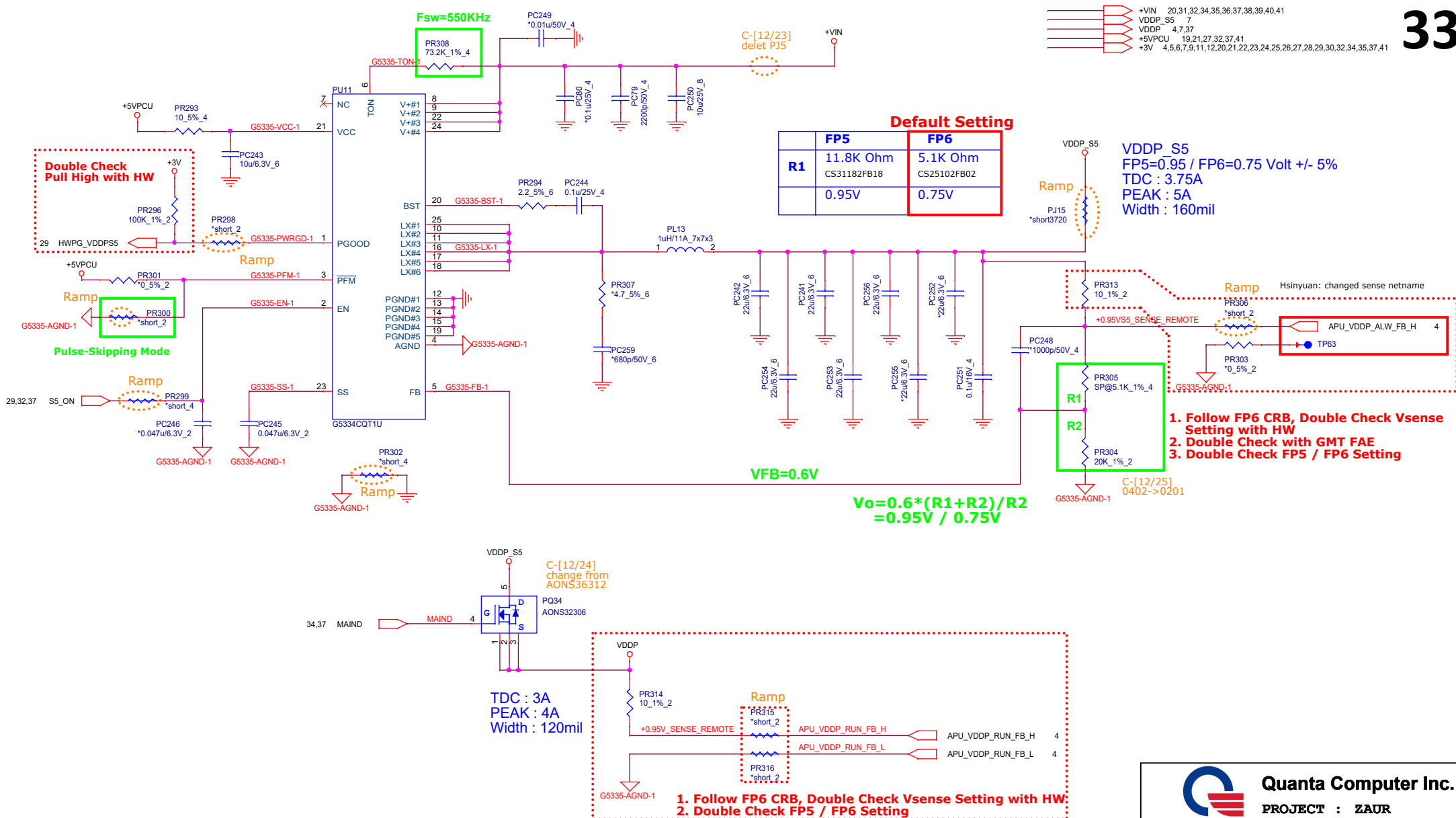


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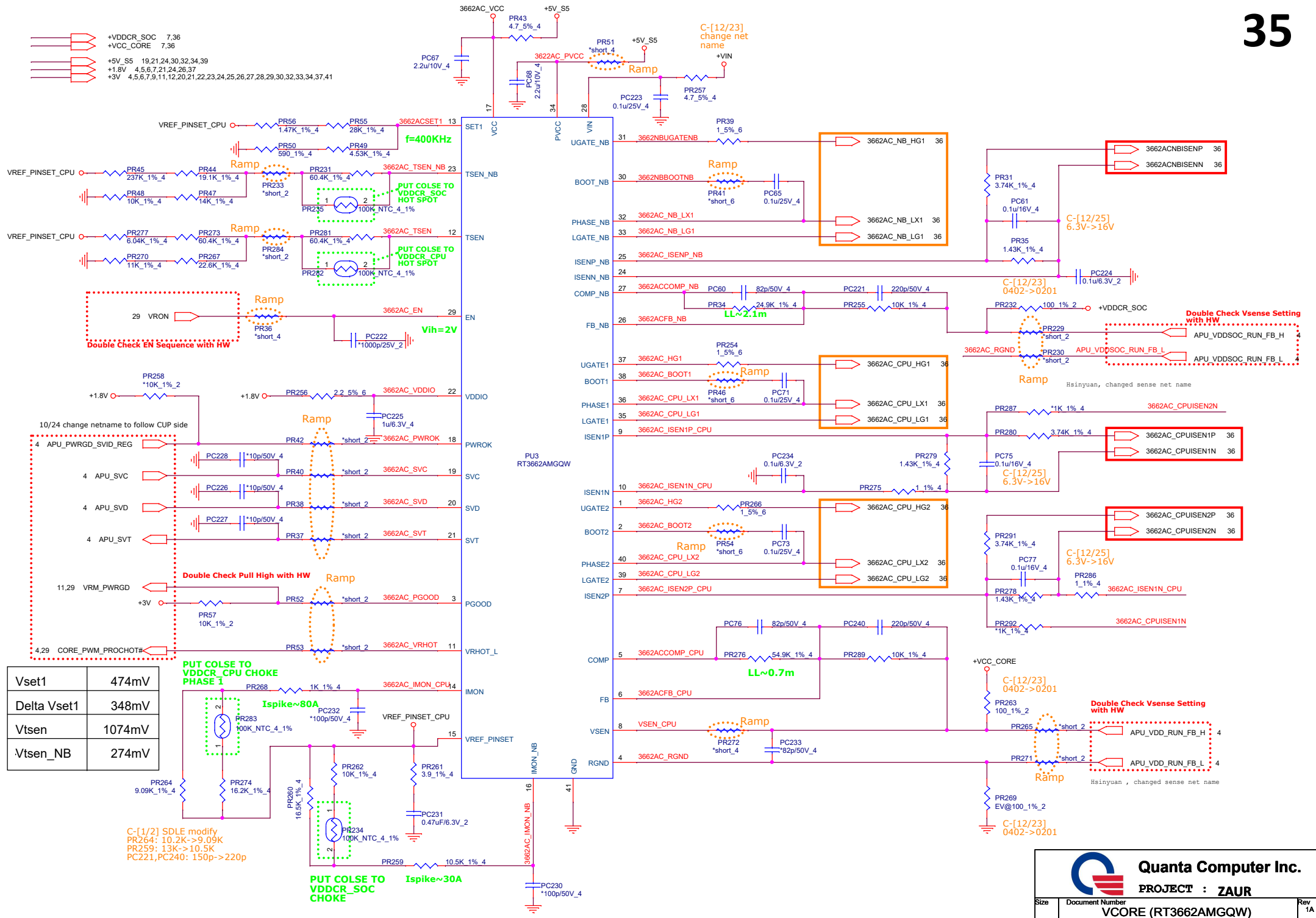


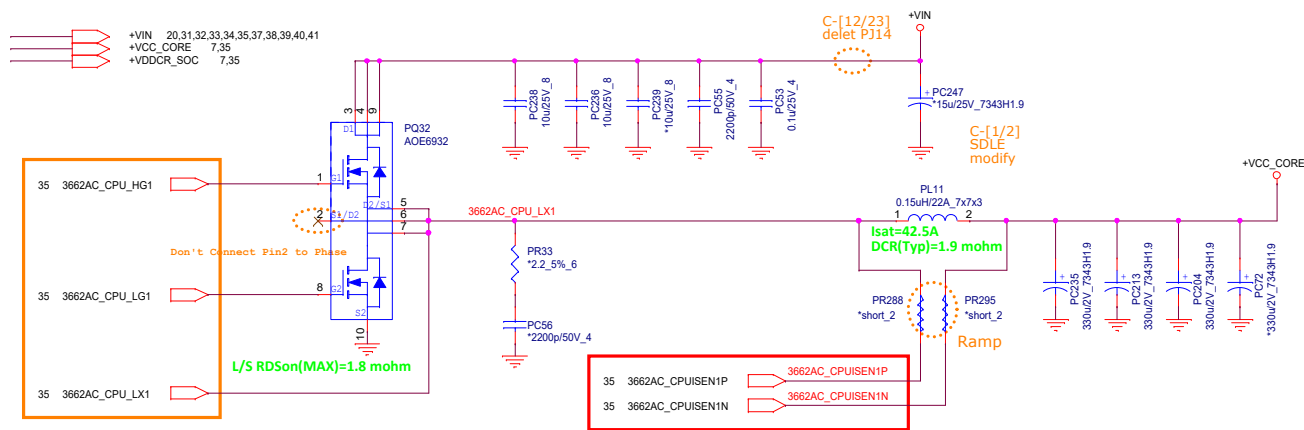
	+VIN	20,31,32,33,35,36,37,38,39,40,41
	+1.2VSUS	3,7,9,10
	+1.2V	22,37
	+2.5V_SUS	9,10
	+VDDQ_VTT	9,10
	+VDDQ	9,10

	VTT_CNTL	SLP_S4	+1.2VSUS	+2.5VSUS	REF	VTT
S0	1	1	ON	ON	ON	ON
S3	0	1	ON	ON	ON	OFF
S4/S5	0	0	OFF	OFF	OFF	OFF

  +VDDCR_SOC 7,36
  +VCC_CORE 7,36

  +5V_S5 19,21,24,30,32,34,39
  +1.8V 4,5,6,7,21,24,26,37
  +3V 4,5,6,7,9,11,12,20,21,22,23,24,25,26,27,28,29,30,32,33,34,37,41





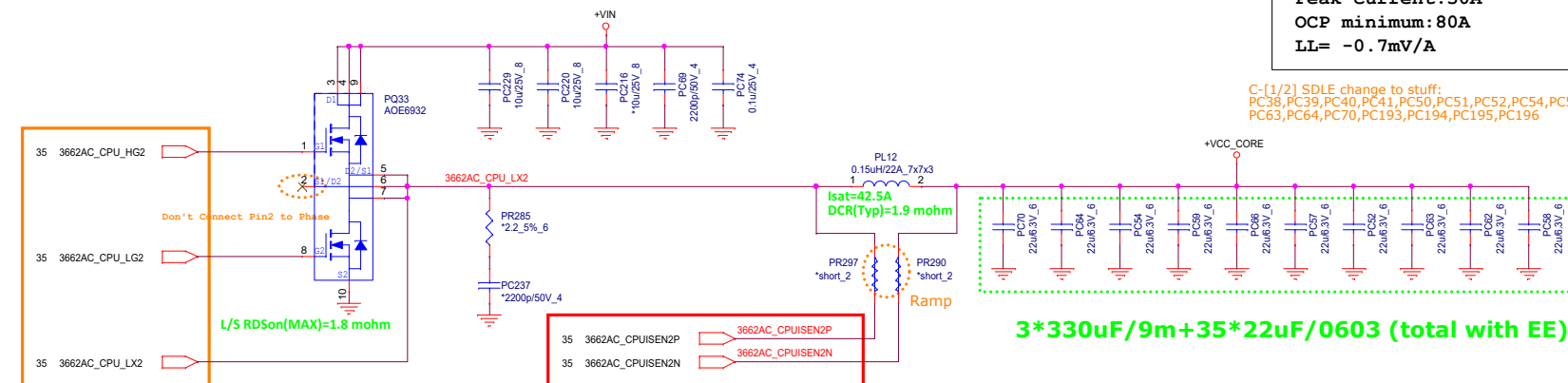
AMD Dali FP5 (15W)

```
VDDCR_VDD
Continue current:35A
Peak current:45A
OCP minimum:80A
LL= -0.7mV/A
```

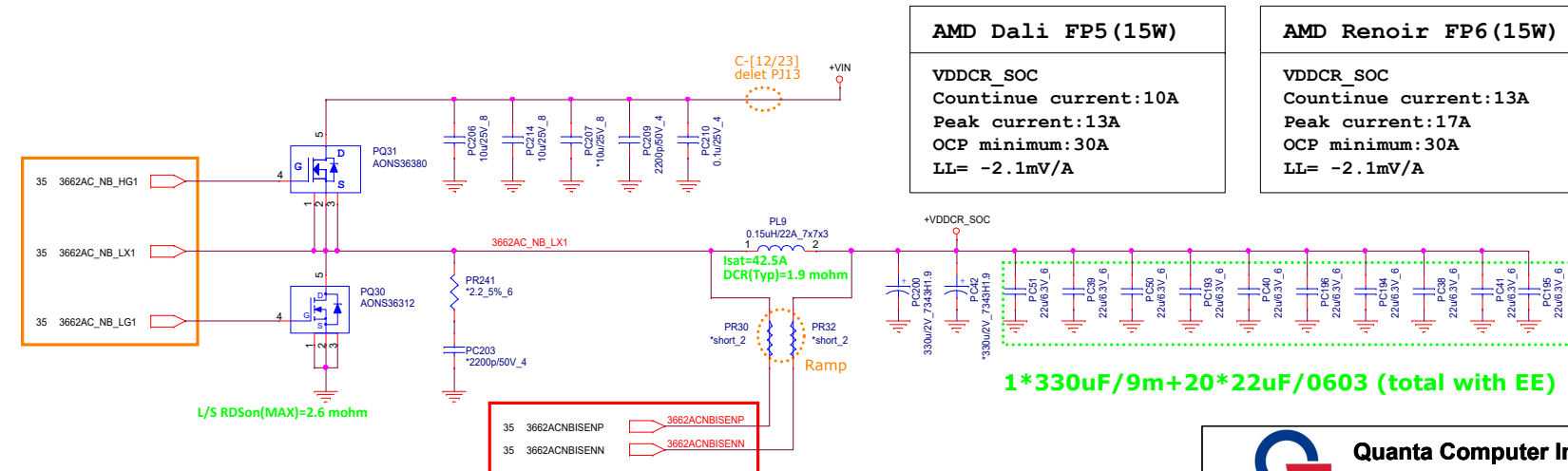
AMD Renoir FP6 (15W)

```
VDDCR_VDD
Continue current:33A
Peak current:50A
OCP minimum:80A
LL= -0.7mV/A
```

C-[1/2] SDLE change to stuff:
PC38,PC39,PC40,PC41,PC50,PC51,PC52,PC54,PC59,
PC63,PC64,PC70,PC193,PC194,PC195,PC196



3*330uF/9m+35*22uF/0603 (total with EE)



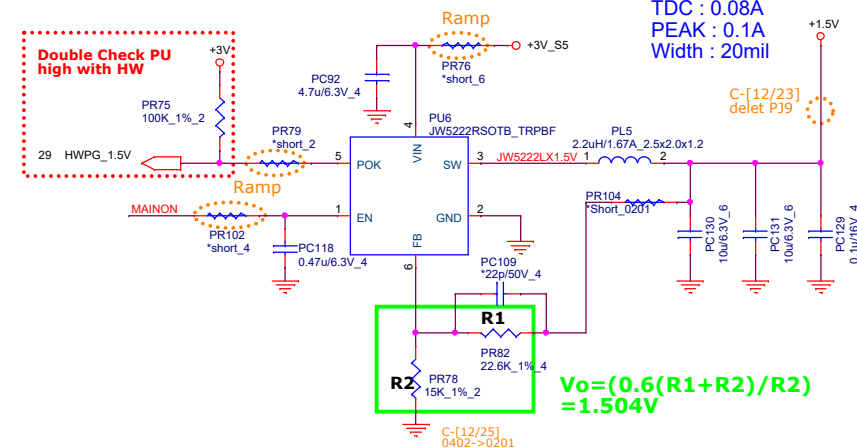
AMD Dali FP5 (15W)

```
VDDCR_SOC
Continue current:10A
Peak current:13A
OCP minimum:30A
LL= -2.1mV/A
```

AMD Renoir FP6 (15W)

```
VDDCR_SOC
Continue current:13A
Peak current:17A
OCP minimum:30A
LL= -2.1mV/A
```

1*330uF/9m+20*22uF/0603 (total with EE)



Need fine tune
for thermal protect point
Note placement position
TEMP=85.27°C

0317 changed to 25.5K

Ramp
PR310
"short_2"

SYS_SHDN#

11,29,32

PU12
TMP708A1DBVR

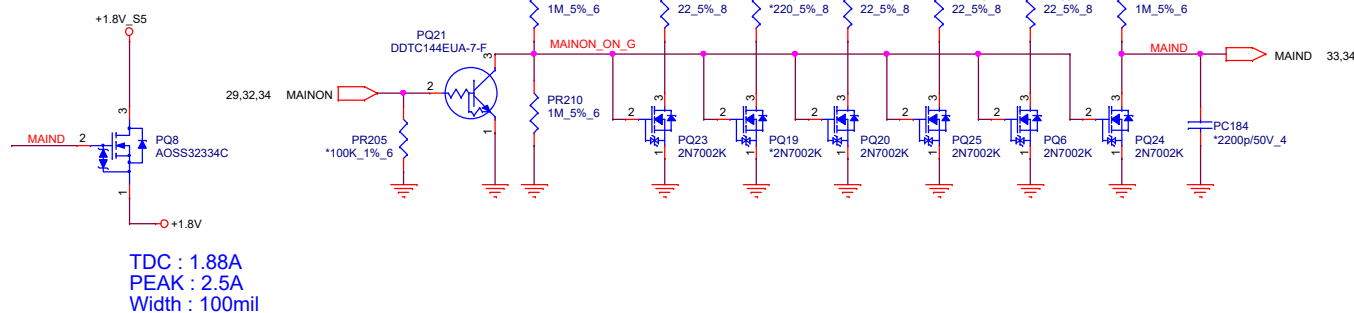
VCC
Q1
SET
GND
HYST


PR326
150.5k_4
PC270
0.1u/16V_4

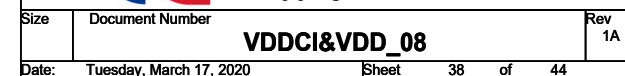
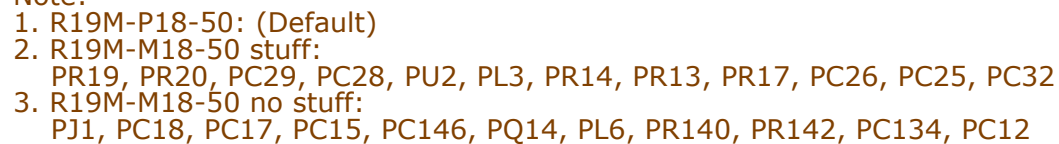
PR311
25.5K_1%_4

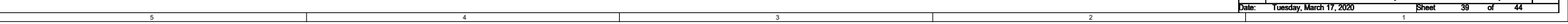
Rset(Kohm)=0.0012*T-0.9308*10⁴+96.147
=25.503 K ohm

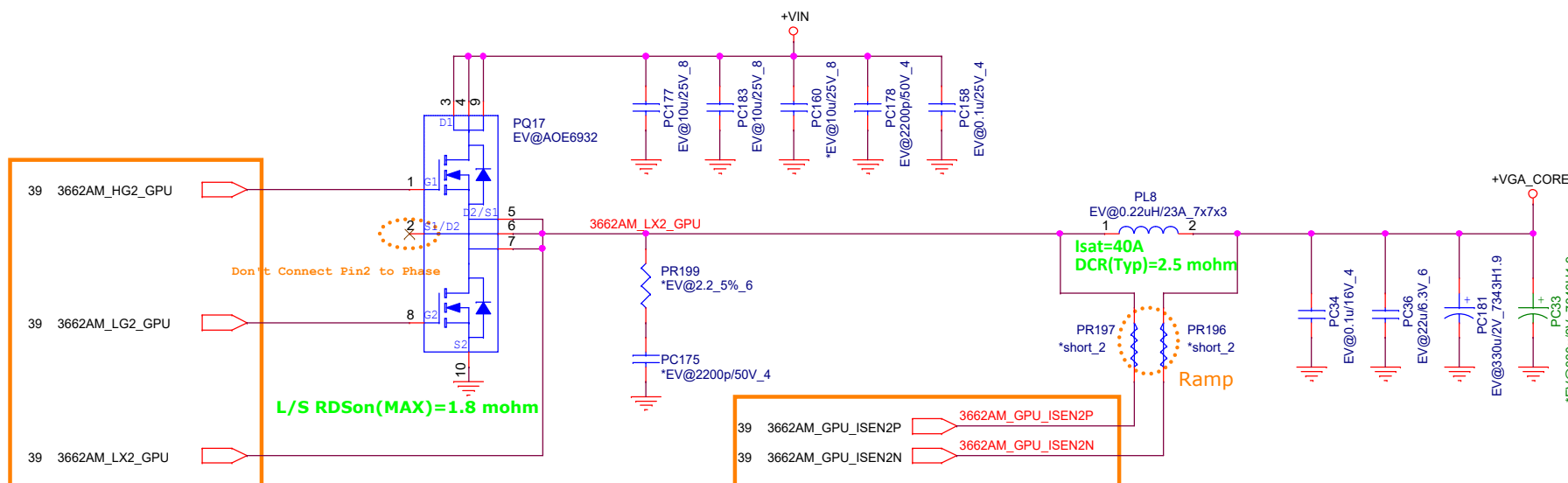
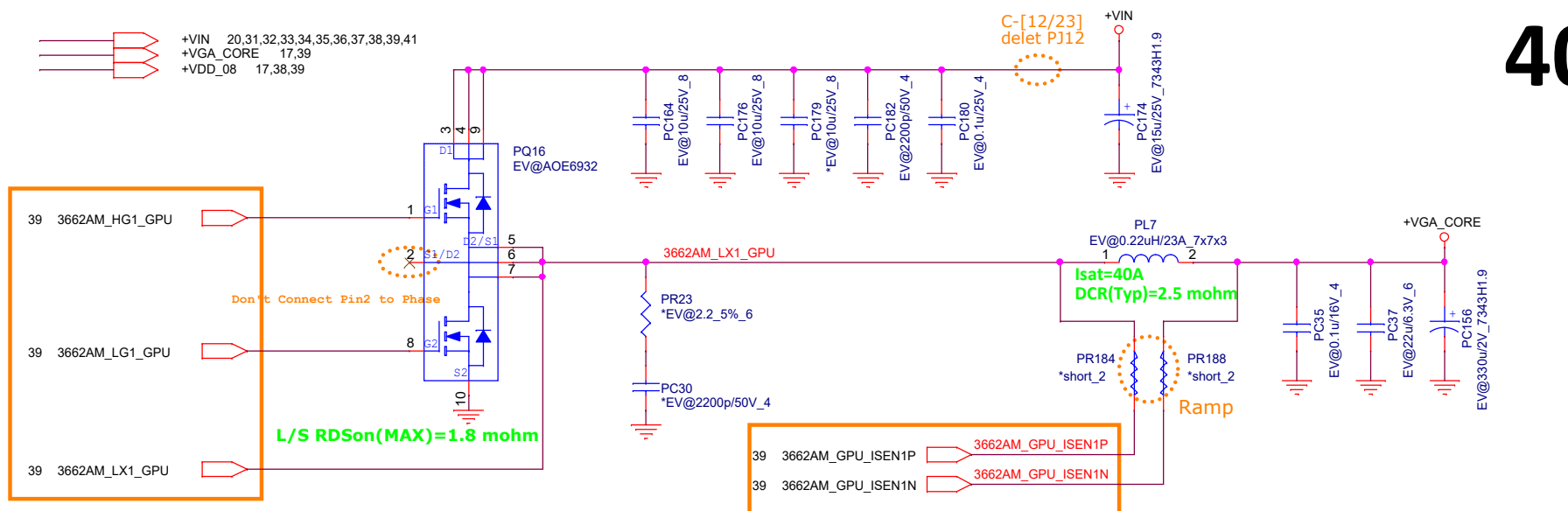
HYST=VCC for 10
degree Hys.
HYST=GND for 30
degree Hys.



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+1.8V_S5/+1.5V/Thermal		
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+VGA_CORE(R19M-P18-50)_18W

VDDC

TDC : 22A
 EDC : 60A
 OCP : 90A
 LL=-0.6m

+VGA_CORE(R19M-M18-50)_18W

VDDC + VDDCI (merged)

TDC : 18A
 EDC : 60A
 OCP : 90A
 LL=-1m



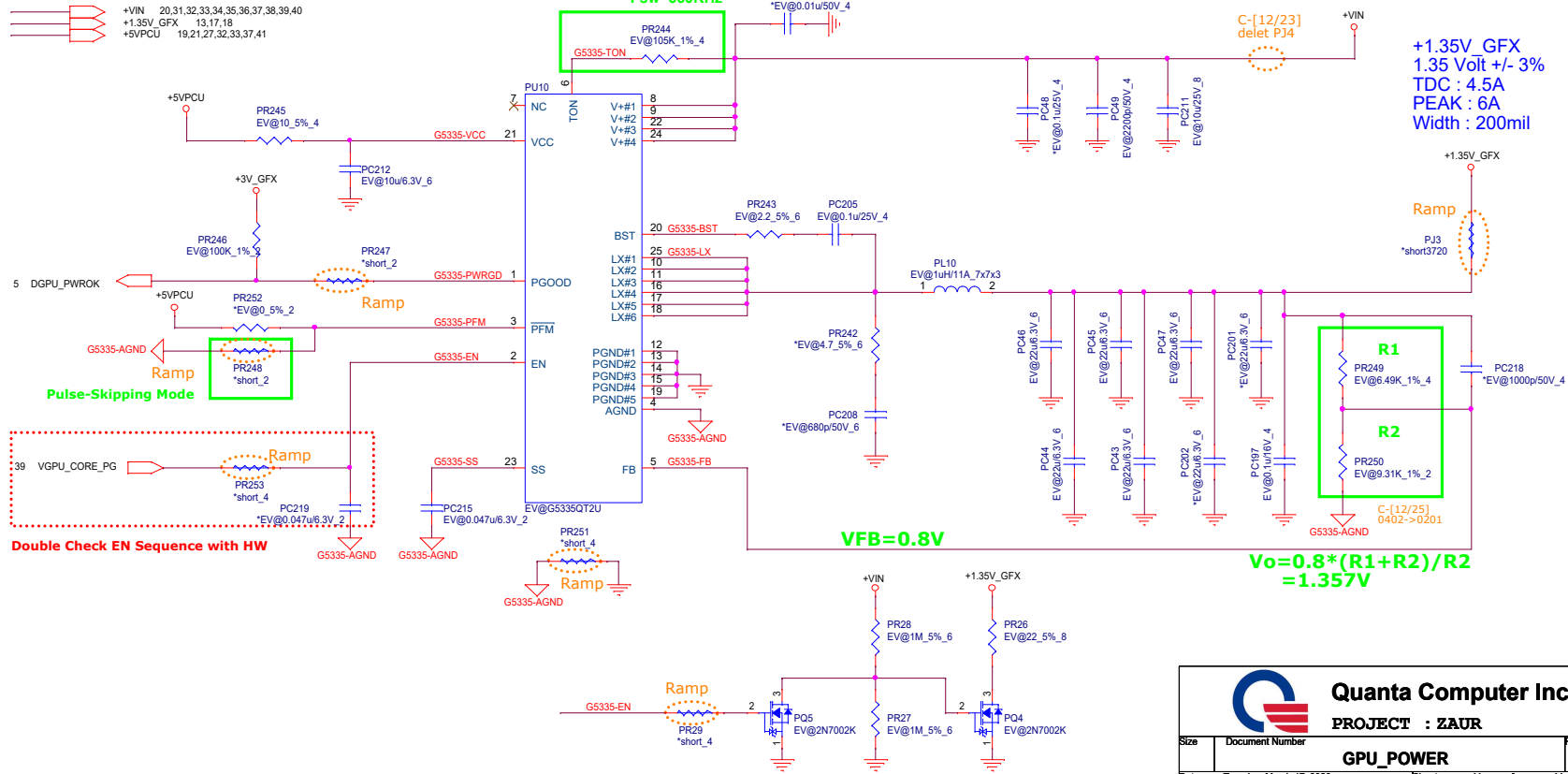
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Size Document Number
VGAORE2 (RT3662AMGQW)

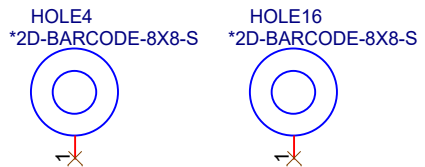
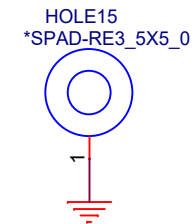
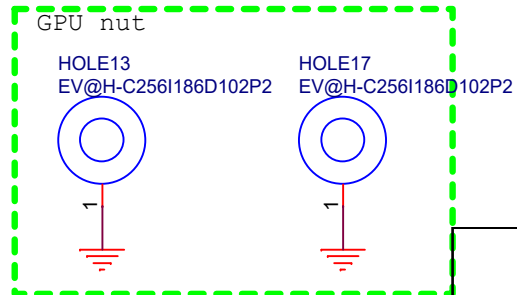
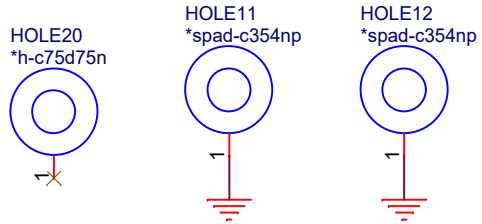
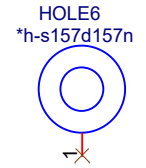
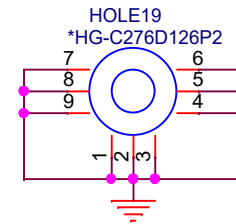
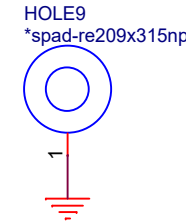
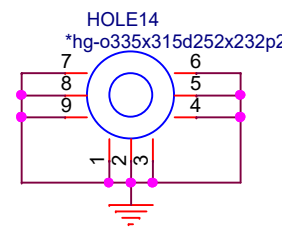
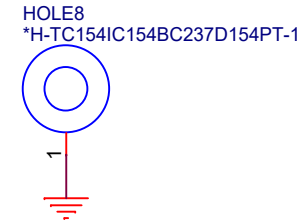
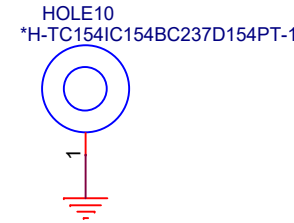
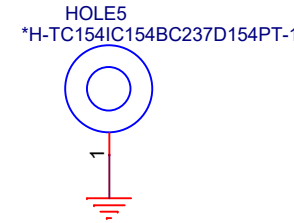
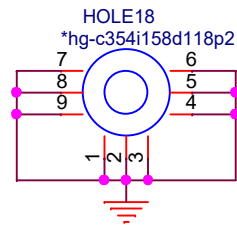
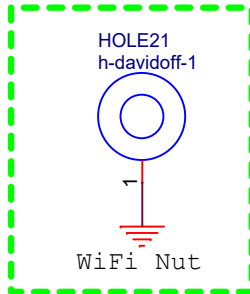
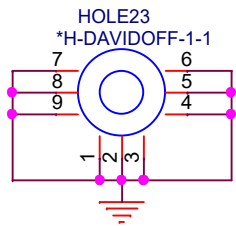
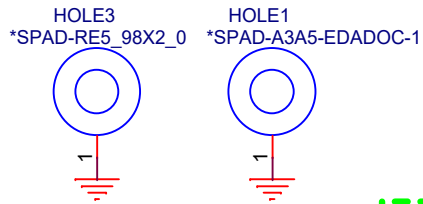
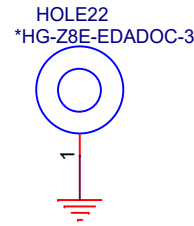
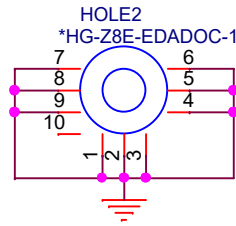
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